

HP ProLiant ML310e Gen8 Server Maintenance and Service Guide

Abstract

This document is for an experienced service technician. It is helpful if you are qualified in the servicing of computer equipment and trained in recognizing hazards in products with hazardous energy levels and are familiar with weight and stability precautions for rack installations.



Part Number: 682265-002
March 2013
Edition: 2

© Copyright 2012, 2013 Hewlett-Packard Development Company, L.P.

The information contained herein is subject to change without notice. The only warranties for HP products and services are set forth in the express warranty statements accompanying such products and services. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

Microsoft® and Windows® are U.S. registered trademarks of Microsoft Corporation.

Intel®, Xeon®, Pentium®, Celeron®, and Intel® Core™ are trademarks of Intel Corporation in the U.S. and other countries.

Contents

Customer self repair	6
Parts only warranty service	6
Illustrated parts catalog	16
Mechanical components.....	16
System components	19
Removal and replacement procedures	24
Required tools.....	24
Safety considerations.....	24
Preventing electrostatic discharge	24
Symbols on equipment	24
Server warnings and cautions	25
Preparation procedures	26
Remove the tower bezel	26
Power down the server	26
Drive blank or carrier.....	27
Storage drive.....	28
Non-hot-plug drive	28
Hot-plug drive	29
Hot-plug power supply	30
Access panel	31
Air baffle	32
Optical drive	32
Drive cage	33
Drive cage bracket or backplane.....	34
Front I/O module	36
Front system fan	37
DIMMs.....	38
General DIMM slot population guidelines	38
Removing a DIMM.....	39
Heatsink.....	39
Processor	41
Expansion board.....	44
Flash-backed write cache procedures	45
FBWC module	45
Capacitor pack	46
Recovering data from the flash-backed write cache	48
System battery	49
Rear system fan.....	50
Dedicated iLO management port.....	50
Enabling the dedicated iLO management port	51
Non-hot-plug power supply.....	51
RPS backplane module.....	52
RPS cage	53
System board	54
HP Trusted Platform Module	60

Troubleshooting	61
Troubleshooting resources	61
Diagnostic tools	62
HP Insight Diagnostics	62
HP Insight Diagnostics survey functionality	62
HP Insight Remote Support software	62
HP ROM-Based Setup Utility	63
Integrated Management Log	63
USB support and functionality	64
USB support	64
Internal USB functionality	64
External USB functionality	64
Automatic Server Recovery	64
Component identification	65
Front panel components	65
Front panel LEDs and buttons	66
Rear panel components	67
Rear panel LEDs and buttons	68
System board components	69
DIMM slot locations	70
PCIe expansion slot definitions	70
System maintenance switch	70
NMI functionality	71
Drive numbering	72
Hot-plug drive LED definitions	73
FBWC module LED definitions	74
Fan locations	75
T-10/T-15 Torx screwdriver	75
Cabling	76
Cabling overview	76
Front panel cabling	76
System fan cabling	77
Storage cabling	77
Four-bay LFF drive cabling	77
Eight-bay SFF drive cabling	79
Media drive cabling	80
Power supply cabling	81
Nonredundant power supply cabling	81
Redundant power supply cabling	82
Capacitor pack cabling	82
Specifications	83
Environmental specifications	83
Server specifications	83
Power supply specifications	83
HP 350 W 4U Integrated Power Supply	84
HP 460 W CS Gold Hot-plug Power Supply (92% efficiency)	84
Hot-plug power supply calculations	84
Support and other resources	85
Before you contact HP	85
HP contact information	85

Acronyms and abbreviations	86
Documentation feedback	89
Index	90

Customer self repair

HP products are designed with many Customer Self Repair (CSR) parts to minimize repair time and allow for greater flexibility in performing defective parts replacement. If during the diagnosis period HP (or HP service providers or service partners) identifies that the repair can be accomplished by the use of a CSR part, HP will ship that part directly to you for replacement. There are two categories of CSR parts:

- **Mandatory**—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.
- **Optional**—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

NOTE: Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

Based on availability and where geography permits, CSR parts will be shipped for next business day delivery. Same day or four-hour delivery may be offered at an additional charge where geography permits. If assistance is required, you can call the HP Technical Support Center and a technician will help you over the telephone. HP specifies in the materials shipped with a replacement CSR part whether a defective part must be returned to HP. In cases where it is required to return the defective part to HP, you must ship the defective part back to HP within a defined period of time, normally five (5) business days. The defective part must be returned with the associated documentation in the provided shipping material. Failure to return the defective part may result in HP billing you for the replacement. With a customer self repair, HP will pay all shipping and part return costs and determine the courier/carrier to be used.

For more information about HP's Customer Self Repair program, contact your local service provider. For the North American program, refer to the HP website (<http://www.hp.com/go/selfrepair>).

Parts only warranty service

Your HP Limited Warranty may include a parts only warranty service. Under the terms of parts only warranty service, HP will provide replacement parts free of charge.

For parts only warranty service, CSR part replacement is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.

Réparation par le client (CSR)

Les produits HP comportent de nombreuses pièces CSR (Customer Self Repair = réparation par le client) afin de minimiser les délais de réparation et faciliter le remplacement des pièces défectueuses. Si pendant la période de diagnostic, HP (ou ses partenaires ou mainteneurs agréés) détermine que la réparation peut être effectuée à l'aide d'une pièce CSR, HP vous l'envoie directement. Il existe deux catégories de pièces CSR:

Obligatoire - Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

Facultatif - Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

REMARQUE: Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

Les pièces CSR sont livrées le jour ouvré suivant, dans la limite des stocks disponibles et selon votre situation géographique. Si votre situation géographique le permet et que vous demandez une livraison le jour même ou dans les 4 heures, celle-ci vous sera facturée. Pour bénéficier d'une assistance téléphonique, appelez le Centre d'assistance technique HP. Dans les documents envoyés avec la pièce de rechange CSR, HP précise s'il est nécessaire de lui retourner la pièce défectueuse. Si c'est le cas, vous devez le faire dans le délai indiqué, généralement cinq (5) jours ouvrés. La pièce et sa documentation doivent être retournées dans l'emballage fourni. Si vous ne retournez pas la pièce défectueuse, HP se réserve le droit de vous facturer les coûts de remplacement. Dans le cas d'une pièce CSR, HP supporte l'ensemble des frais d'expédition et de retour, et détermine la société de courses ou le transporteur à utiliser.

Pour plus d'informations sur le programme CSR de HP, contactez votre Mainteneur Agréé local. Pour plus d'informations sur ce programme en Amérique du Nord, consultez le site Web HP (<http://www.hp.com/go/selfrepair>).

Service de garantie "pièces seules"

Votre garantie limitée HP peut inclure un service de garantie "pièces seules". Dans ce cas, les pièces de rechange fournies par HP ne sont pas facturées.

Dans le cadre de ce service, la réparation des pièces CSR par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

Riparazione da parte del cliente

Per abbreviare i tempi di riparazione e garantire una maggiore flessibilità nella sostituzione di parti difettose, i prodotti HP sono realizzati con numerosi componenti che possono essere riparati direttamente dal cliente (CSR, Customer Self Repair). Se in fase di diagnostica HP (o un centro di servizi o di assistenza HP) identifica il guasto come riparabile mediante un ricambio CSR, HP lo spedisce direttamente al cliente per la sostituzione. Vi sono due categorie di parti CSR:

Obbligatorie – Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

Opzionali – Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese aggiuntive a seconda del tipo di garanzia previsto per il prodotto.

NOTA: alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

In base alla disponibilità e alla località geografica, le parti CSR vengono spedite con consegna entro il giorno lavorativo seguente. La consegna nel giorno stesso o entro quattro ore è offerta con un supplemento di costo solo in alcune zone. In caso di necessità si può richiedere l'assistenza telefonica di un addetto del centro di supporto tecnico HP. Nel materiale fornito con una parte di ricambio CSR, HP specifica se il cliente deve restituire dei componenti. Qualora sia richiesta la resa ad HP del componente difettoso, lo si deve spedire ad HP entro un determinato periodo di tempo, generalmente cinque (5) giorni lavorativi. Il componente difettoso deve essere restituito con la documentazione associata nell'imballo di spedizione fornito. La mancata restituzione del componente può comportare la fatturazione del ricambio da parte di HP. Nel caso di riparazione da parte del cliente, HP sostiene tutte le spese di spedizione e resa e sceglie il corriere/vettore da utilizzare.

Per ulteriori informazioni sul programma CSR di HP contattare il centro di assistenza di zona. Per il programma in Nord America fare riferimento al sito Web HP (<http://www.hp.com/go/selfrepair>).

Servizio di garanzia per i soli componenti

La garanzia limitata HP può includere un servizio di garanzia per i soli componenti. Nei termini di garanzia del servizio per i soli componenti, HP fornirà gratuitamente le parti di ricambio.

Per il servizio di garanzia per i soli componenti è obbligatoria la formula CSR che prevede la riparazione da parte del cliente. Se il cliente invece richiede la sostituzione ad HP, dovrà sostenere le spese di spedizione e di manodopera per il servizio.

Customer Self Repair

HP Produkte enthalten viele CSR-Teile (Customer Self Repair), um Reparaturzeiten zu minimieren und höhere Flexibilität beim Austausch defekter Bauteile zu ermöglichen. Wenn HP (oder ein HP Servicepartner) bei der Diagnose feststellt, dass das Produkt mithilfe eines CSR-Teils repariert werden kann, sendet Ihnen HP dieses Bauteil zum Austausch direkt zu. CSR-Teile werden in zwei Kategorien unterteilt:

Zwingend – Teile, für die das Customer Self Repair-Verfahren zwingend vorgegeben ist. Wenn Sie den Austausch dieser Teile von HP vornehmen lassen, werden Ihnen die Anfahrt- und Arbeitskosten für diesen Service berechnet.

Optional – Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

HINWEIS: Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

CSR-Teile werden abhängig von der Verfügbarkeit und vom Lieferziel am folgenden Geschäftstag geliefert. Für bestimmte Standorte ist eine Lieferung am selben Tag oder innerhalb von vier Stunden gegen einen Aufpreis verfügbar. Wenn Sie Hilfe benötigen, können Sie das HP technische Support Center anrufen und sich von einem Mitarbeiter per Telefon helfen lassen. Den Materialien, die mit einem CSR-Ersatzteil geliefert werden, können Sie entnehmen, ob das defekte Teil an HP zurückgeschickt werden muss. Wenn es erforderlich ist, das defekte Teil an HP zurückzuschicken, müssen Sie dies innerhalb eines vorgegebenen Zeitraums tun, in der Regel innerhalb von fünf (5) Geschäftstagen. Das defekte Teil muss mit der zugehörigen Dokumentation in der Verpackung zurückgeschickt werden, die im Lieferumfang enthalten ist. Wenn Sie das

defekte Teil nicht zurückschicken, kann HP Ihnen das Ersatzteil in Rechnung stellen. Im Falle von Customer Self Repair kommt HP für alle Kosten für die Lieferung und Rücksendung auf und bestimmt den Kurier-/Frachtdienst.

Weitere Informationen über das HP Customer Self Repair Programm erhalten Sie von Ihrem Servicepartner vor Ort. Informationen über das CSR-Programm in Nordamerika finden Sie auf der HP Website unter (<http://www.hp.com/go/selfrepair>).

Parts-only Warranty Service (Garantieservice ausschließlich für Teile)

Ihre HP Garantie umfasst möglicherweise einen Parts-only Warranty Service (Garantieservice ausschließlich für Teile). Gemäß den Bestimmungen des Parts-only Warranty Service stellt HP Ersatzteile kostenlos zur Verfügung.

Für den Parts-only Warranty Service ist das CSR-Verfahren zwingend vorgegeben. Wenn Sie den Austausch dieser Teile von HP vornehmen lassen, werden Ihnen die Anfahrt- und Arbeitskosten für diesen Service berechnet.

Reparaciones del propio cliente

Los productos de HP incluyen muchos componentes que el propio usuario puede reemplazar (*Customer Self Repair*, CSR) para minimizar el tiempo de reparación y ofrecer una mayor flexibilidad a la hora de realizar sustituciones de componentes defectuosos. Si, durante la fase de diagnóstico, HP (o los proveedores o socios de servicio de HP) identifica que una reparación puede llevarse a cabo mediante el uso de un componente CSR, HP le enviará dicho componente directamente para que realice su sustitución. Los componentes CSR se clasifican en dos categorías:

- **Obligatorio:** componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.
- **Opcional:** componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

NOTA: Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra "No" en el catálogo ilustrado de componentes.

Según la disponibilidad y la situación geográfica, los componentes CSR se enviarán para que lleguen a su destino al siguiente día laborable. Si la situación geográfica lo permite, se puede solicitar la entrega en el mismo día o en cuatro horas con un coste adicional. Si precisa asistencia técnica, puede llamar al Centro de asistencia técnica de HP y recibirá ayuda telefónica por parte de un técnico. Con el envío de materiales para la sustitución de componentes CSR, HP especificará si los componentes defectuosos deberán devolverse a HP. En aquellos casos en los que sea necesario devolver algún componente a HP, deberá hacerlo en el periodo de tiempo especificado, normalmente cinco días laborables. Los componentes defectuosos deberán devolverse con toda la documentación relacionada y con el embalaje de envío. Si no

enviara el componente defectuoso requerido, HP podrá cobrarle por el de sustitución. En el caso de todas sustituciones que lleve a cabo el cliente, HP se hará cargo de todos los gastos de envío y devolución de componentes y escogerá la empresa de transporte que se utilice para dicho servicio.

Para obtener más información acerca del programa de Reparaciones del propio cliente de HP, póngase en contacto con su proveedor de servicios local. Si está interesado en el programa para Norteamérica, visite la página web de HP siguiente (<http://www.hp.com/go/selfrepair>).

Servicio de garantía exclusivo de componentes

La garantía limitada de HP puede que incluya un servicio de garantía exclusivo de componentes. Según las condiciones de este servicio exclusivo de componentes, HP le facilitará los componentes de repuesto sin cargo adicional alguno.

Para este servicio de garantía exclusivo de componentes, es obligatoria la sustitución de componentes por parte del usuario (CSR). Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.

Customer Self Repair

Veel onderdelen in HP producten zijn door de klant zelf te repareren, waardoor de reparatieduur tot een minimum beperkt kan blijven en de flexibiliteit in het vervangen van defecte onderdelen groter is. Deze onderdelen worden CSR-onderdelen (Customer Self Repair) genoemd. Als HP (of een HP Service Partner) bij de diagnose vaststelt dat de reparatie kan worden uitgevoerd met een CSR-onderdeel, verzendt HP dat onderdeel rechtstreeks naar u, zodat u het defecte onderdeel daarmee kunt vervangen. Er zijn twee categorieën CSR-onderdelen:

Verplicht: Onderdelen waarvoor reparatie door de klant verplicht is. Als u HP verzoekt deze onderdelen voor u te vervangen, worden u voor deze service reiskosten en arbeidsloon in rekening gebracht.

Optioneel: Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garantieservice voor het product.

OPMERKING: Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievoorwaarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

Afhankelijk van de leverbaarheid en de locatie worden CSR-onderdelen verzonden voor levering op de eerstvolgende werkdag. Levering op dezelfde dag of binnen vier uur kan tegen meerkosten worden aangeboden, indien dit mogelijk is gezien de locatie. Indien assistentie gewenst is, belt u een HP Service Partner om via de telefoon technische ondersteuning te ontvangen. HP vermeldt in de documentatie bij het vervangende CSR-onderdeel of het defecte onderdeel aan HP moet worden geretourneerd. Als het defecte onderdeel aan HP moet worden teruggezonden, moet u het defecte onderdeel binnen een bepaalde periode, gewoonlijk vijf (5) werkdagen, retourneren aan HP. Het defecte onderdeel moet met de bijbehorende documentatie worden geretourneerd in het meegeleverde verpakkingsmateriaal. Als u het defecte onderdeel niet terugzendt, kan HP u voor het vervangende onderdeel kosten in rekening brengen. Bij reparatie door de klant betaalt HP alle verzendkosten voor het vervangende en geretourneerde onderdeel en kiest HP zelf welke koerier/transportonderneming hiervoor wordt gebruikt.

Neem contact op met een Service Partner voor meer informatie over het Customer Self Repair programma van HP. Informatie over Service Partners vindt u op de HP website (<http://www.hp.com/go/selfrepair>).

Garantieservice "Parts Only"

Het is mogelijk dat de HP garantie alleen de garantieservice "Parts Only" omvat. Volgens de bepalingen van de Parts Only garantieservice zal HP kosteloos vervangende onderdelen ter beschikking stellen.

Voor de Parts Only garantieservice is vervanging door CSR-onderdelen verplicht. Als u HP verzoekt deze onderdelen voor u te vervangen, worden u voor deze service reiskosten en arbeidsloon in rekening gebracht.

Reparo feito pelo cliente

Os produtos da HP são projetados com muitas peças para reparo feito pelo cliente (CSR) de modo a minimizar o tempo de reparo e permitir maior flexibilidade na substituição de peças com defeito. Se, durante o período de diagnóstico, a HP (ou fornecedores/parceiros de serviço da HP) concluir que o reparo pode ser efetuado pelo uso de uma peça CSR, a peça de reposição será enviada diretamente ao cliente. Existem duas categorias de peças CSR:

Obrigatória – Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

Opcional – Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

OBSERVAÇÃO: Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca "No" (Não), no catálogo de peças ilustrado.

Conforme a disponibilidade e o local geográfico, as peças CSR serão enviadas no primeiro dia útil após o pedido. Onde as condições geográficas permitirem, a entrega no mesmo dia ou em quatro horas pode ser feita mediante uma taxa adicional. Se precisar de auxílio, entre em contato com o Centro de suporte técnico da HP para que um técnico o ajude por telefone. A HP especifica nos materiais fornecidos com a peça CSR de reposição se a peça com defeito deve ser devolvida à HP. Nos casos em que isso for necessário, é preciso enviar a peça com defeito à HP dentro do período determinado, normalmente cinco (5) dias úteis. A peça com defeito deve ser enviada com a documentação correspondente no material de transporte fornecido. Caso não o faça, a HP poderá cobrar a reposição. Para as peças de reparo feito pelo cliente, a HP paga todas as despesas de transporte e de devolução da peça e determina a transportadora/serviço postal a ser utilizado.

Para obter mais informações sobre o programa de reparo feito pelo cliente da HP, entre em contato com o fornecedor de serviços local. Para o programa norte-americano, visite o site da HP (<http://www.hp.com/go/selfrepair>).

Serviço de garantia apenas para peças

A garantia limitada da HP pode incluir um serviço de garantia apenas para peças. Segundo os termos do serviço de garantia apenas para peças, a HP fornece as peças de reposição sem cobrar nenhuma taxa.

No caso desse serviço, a substituição de peças CSR é obrigatória. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

カスタマーセルフリペア

修理時間を短縮し、故障部品の交換における高い柔軟性を確保するために、HP製品には多数のCSR部品があります。診断の際に、CSR部品を使用すれば修理ができるとHP（HPまたはHP正規保守代理店）が判断した場合、HPはその部品を直接、お客様に発送し、お客様に交換していただきます。CSR部品には以下の2通りがあります。

- **必須** - カスタマーセルフリペアが必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。
- **任意** - カスタマーセルフリペアが任意である部品。この部品もカスタマーセルフリペア用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、別途費用を負担していただくことなく保証サービスを受けることができます。

注： HP製品の一部の部品は、カスタマーセルフリペア用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品がカスタマーセルフリペア除外品である旨が記載されています。

部品供給が可能な場合、地域によっては、CSR部品を翌営業日に届くように発送します。また、地域によっては、追加費用を負担いただくことにより同日または4時間以内に届くように発送することも可能な場合があります。サポートが必要なときは、HPの修理受付窓口にご電話いただければ、技術者が電話でアドバイスします。交換用のCSR部品または同梱物には、故障部品をHPに返送する必要があるかどうかが表示されています。故障部品をHPに返送する必要がある場合は、指定期限内（通常は5営業日以内）に故障部品をHPに返送してください。故障部品を返送する場合は、届いた時の梱包箱に関連書類とともに入れてください。故障部品を返送しない場合、HPから部品費用が請求されます。カスタマーセルフリペアの際には、HPは送料および部品返送費を全額負担し、使用する宅配便会社や運送会社を指定します。

部品のみ保証サービス

HP保証サービスには、部品のみ保証サービスが適用される場合があります。このサービスでは、交換部品は無償で提供されます。

部品のみ保証サービスにおいては、CSR部品をお客様により交換作業していただくことが必須となります。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費はお客様の負担となります。

客户自行维修

HP 产品提供许多客户自行维修 (CSR) 部件，以尽可能缩短维修时间和在更换缺陷部件方面提供更大的灵活性。如果在诊断期间 HP（或 HP 服务提供商或服务合作伙伴）确定可以通过使用 CSR 部件完成维修，HP 将直接把该部件发送给您进行更换。有两类 CSR 部件：

- **强制性的** — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。
- **可选的** — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

注：某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

CSR 部件将在下一个工作日发运（取决于备货情况和允许的地理范围）。在允许的地理范围内，可在当天或四小时内发运，但要收取额外费用。如果需要帮助，您可以致电 HP 技术支持中心，将会有技术人员通过电话为您提供帮助。HP 会在随更换的 CSR 部件发运的材料中指明是否必须将有缺陷的部件返还给 HP。如果要求您将有缺陷的部件返还给 HP，那么您必须在规定期限内（通常是五 (5) 个工作日）将缺陷部件发给 HP。有缺陷的部件必须随所提供的发运材料中的相关文件一起返还。如果未能送还有缺陷的部件，HP 可能会要求您支付更换费用。客户自行维修时，HP 将承担所有相关运输和部件返回费用，并指定快递商/承运商。

有关 HP 客户自行维修计划的详细信息，请与您当地的服务提供商联系。有关北美地区的计划，请访问 HP 网站 (<http://www.hp.com/go/selfrepair>)。

仅部件保修服务

您的 HP 有限保修服务可能涉及仅部件保修服务。根据仅部件保修服务条款的规定，HP 将免费提供更换的部件。

仅部件保修服务要求进行 CSR 部件更换。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。

客戶自行維修

HP 產品設計了許多「客戶自行維修」(CSR) 的零件以減少維修時間，並且使得更換瑕疵零件時能有更大的彈性。如果在診斷期間 HP（或 HP 服務供應商或維修夥伴）辨認出此項維修工作可以藉由使用 CSR 零件來完成，則 HP 將直接寄送該零件給您作更換。CSR 零件分為兩種類別：

- **強制的** — 客戶自行維修所使用的零件是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。
- **選購的** — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

備註：某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

基於材料取得及環境允許的情況下，CSR 零件將於下一個工作日以快遞寄送。在環境的允許下當天或四小時內送達，則可能需要額外的費用。若您需要協助，可致電「HP 技術支援中心」，會有一位技術人員透過電話來協助您。不論損壞的零件是否必須退回，HP 皆會在與 CSR 替換零件一起運送的材料中註明。若要將損壞的零件退回 HP，您必須在指定的一段時間內（通常為五 (5) 個工作天），將損壞的零件寄回 HP。損壞的零件必須與寄送資料中隨附的相關技術文件一併退還。如果無法退還損壞的零件，HP 可能要向您收取替換費用。針對客戶自行維修情形，HP 將負責所有運費及零件退還費用並指定使用何家快遞/貨運公司。

如需 HP 的「客戶自行維修」方案詳細資訊，請連絡您當地的服務供應商。至於北美方案，請參閱 HP 網站 (<http://www.hp.com/go/selfrepair>)。

僅限零件的保固服務

您的「HP 有限保固」可能包含僅限零件的保固服務。在僅限零件的保固服務情況下，HP 將免費提供替換零件。

針對僅限零件的保固服務，CSR 零件替換是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。

고객 셀프 수리

HP 제품은 수리 시간을 최소화하고 결함이 있는 부품 교체 시 더욱 용통성을 발휘할 수 있도록 하기 위해 고객 셀프 수리(CSR) 부품을 다량 사용하여 설계되었습니다. 진단 기간 동안 HP(또는 HP 서비스 공급업체 또는 서비스 협력업체)에서 CSR 부품을 사용하여 수리가 가능하다고 판단되면 HP는 해당 부품을 바로 사용자에게 보내어 사용자가 교체할 수 있도록 합니다. CSR 부품에는 두 가지 종류가 있습니다.

- **고객 셀프 수리가 의무 사항인 필수 부품.** 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.
- **고객 셀프 수리가 선택 사항인 부품.** 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

참고: 일부 HP 부품은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 만족스러운 고객 보증을 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다. 이러한 부품들은 Illustrated Parts Catalog에 "No"라고 표시되어 있습니다.

CSR 부품은 재고 상태와 지리적 조건이 허용하는 경우 다음 영업일 납품이 가능하도록 배송이 이루어집니다. 지리적 조건이 허용하는 경우 추가 비용이 청구되는 조건으로 당일 또는 4시간 배송이 가능할 수도 있습니다. 도움이 필요하시면 HP 기술 지원 센터로 전화하십시오. 전문 기술자가 전화로 도움을 줄 것입니다. HP는 결함이 발생한 부품을 HP로 반환해야 하는지 여부를 CSR 교체 부품과 함께 배송된 자료에 지정합니다. 결함이 발생한 부품을 HP로 반환해야 하는 경우에는 지정된 기간 내(통상 영업일 기준 5일)에 HP로 반환해야 합니다. 이 때 결함이 발생한 부품은 제공된 포장 재료에 넣어 관련 설명서와 함께 반환해야 합니다. 결함이 발생한 부품을 반환하지 않는 경우 HP가 교체 부품에 대해 비용을 청구할 수 있습니다. 고객 셀프 수리의 경우, HP는 모든 운송 및 부품 반환 비용을 부담하며 이용할 운송업체 및 택배 서비스를 결정합니다.

HP 고객 셀프 수리 프로그램에 대한 자세한 내용은 가까운 서비스 제공업체에 문의하십시오. 북미 지역의 프로그램에 대해서는 HP 웹 사이트(<http://www.hp.com/go/selfrepair>)를 참조하십시오.

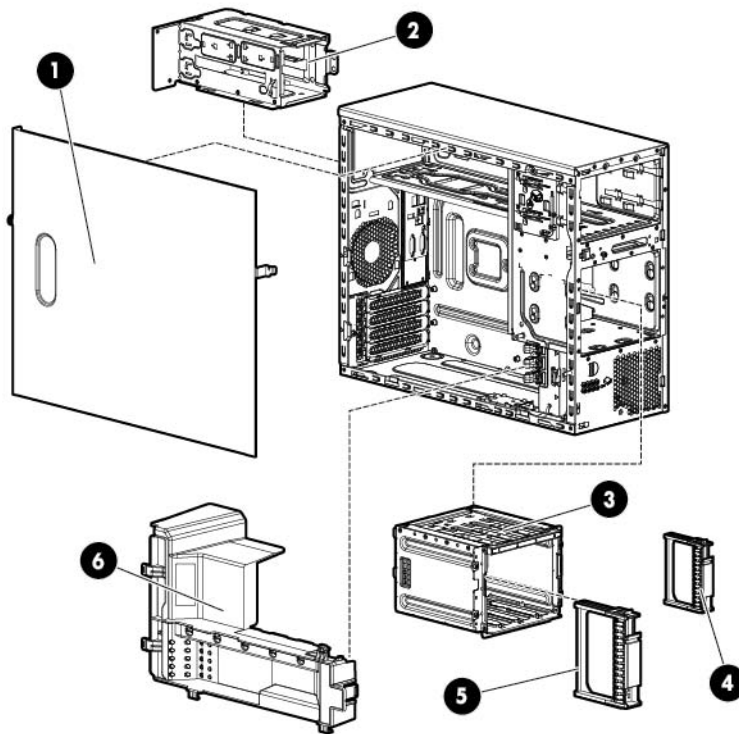
부품 제공 보증 서비스

HP 제한 보증에는 부품 제공 보증 서비스가 포함될 수 있습니다. 이러한 경우 HP는 부품 제공 보증 서비스의 조건에 따라 교체 부품만을 무료로 제공합니다.

부품 제공 보증 서비스 제공 시 CSR 부품 교체는 의무 사항입니다. 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.

Illustrated parts catalog

Mechanical components



Item	Description	Spare part number	Customer self repair (on page 6)
1	Access panel	686751-001	Mandatory ¹
2	RPS cage	686665-001	Mandatory ¹
3	Four-bay LFF drive cage	686745-001	Mandatory ¹
4	SFF drive blank	670033-001	Mandatory ¹
5	LFF drive blank	675039-001	Mandatory ¹
6	Air baffle	686752-001	Mandatory ¹

¹Mandatory—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.

²Optional—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

³No—Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

¹Mandatory: Obligatoire—Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

²Optional: Facultatif—Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

³No: Non—Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

¹Mandatory: Obbligatorie—Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

²Optional: Opzionali—Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese aggiuntive a seconda del tipo di garanzia previsto per il prodotto.

³No: Non CSR—Alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

¹Mandatory: Zwingend—Teile, die im Rahmen des Customer Self Repair Programms ersetzt werden müssen. Wenn Sie diese Teile von HP ersetzen lassen, werden Ihnen die Versand- und Arbeitskosten für diesen Service berechnet.

²Optional: Optional—Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

³No: Kein—Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

¹Mandatory: Obligatorio—componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.

²Optional: Opcional—componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

³No: No—Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra "No" en el catálogo ilustrado de componentes.

¹Mandatory: Verplicht—Onderdelen waarvoor Customer Self Repair verplicht is. Als u HP verzoekt deze onderdelen te vervangen, komen de reiskosten en het arbeidsloon voor uw rekening.

²Optional: Optioneel—Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garantieservice voor het product.

³No: Nee—Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievoorwaarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

¹Mandatory: Obrigatória—Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

²Optional: Opcional—Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

³No: Nenhuma—Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca "No" (Não), no catálogo de peças ilustrado.

¹Mandatory : 必須 - 顧客自己修理が必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。

²Optional : 任意 - 顧客自己修理が任意である部品。この部品も顧客自己修理用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、費用を負担していただくことなく保証サービスを受けることができます。

³No : 除外 - HP製品の一部の部品は、顧客自己修理用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品が顧客自己修理除外品である旨が記載されています。

¹Mandatory: 强制性的 — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。

²Optional: 可选的 — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据为您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

³No: 否 — 某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

¹Mandatory: 強制的 — 客戶自行維修所使用的零件是強制的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。

²Optional: 選購的 — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

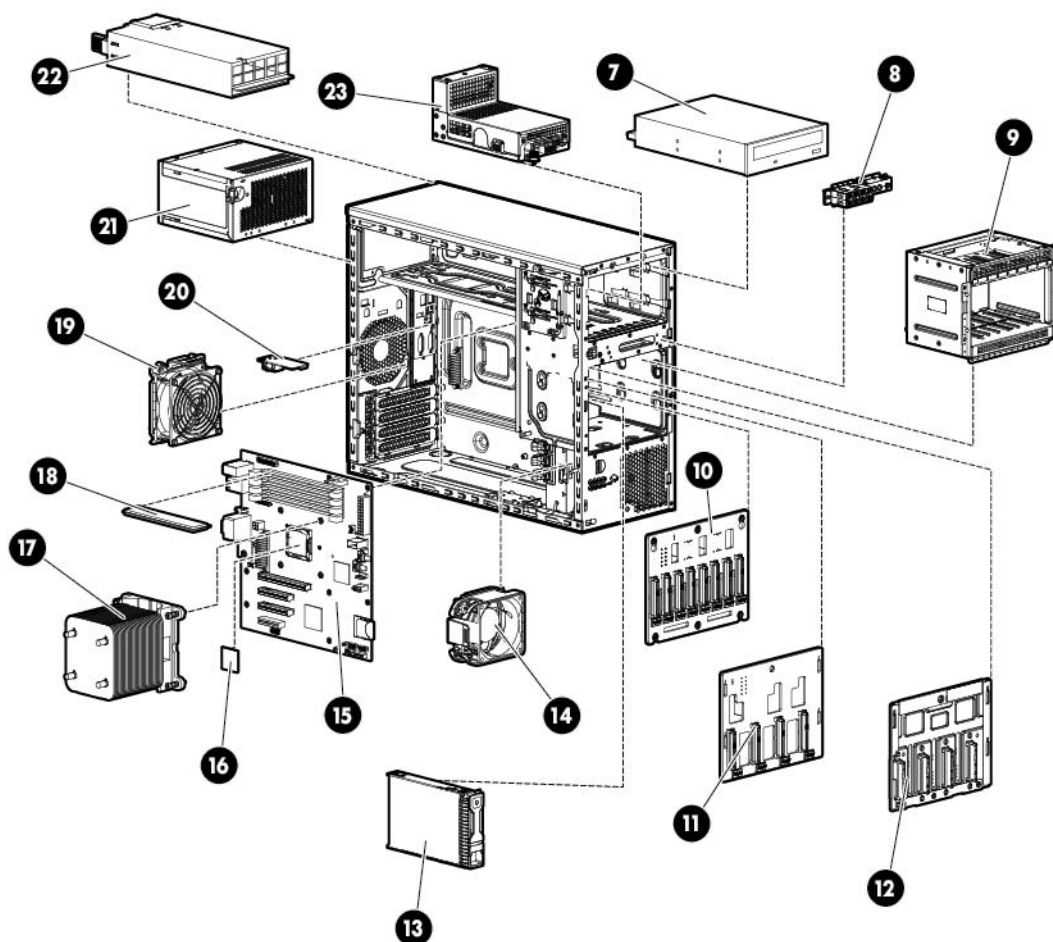
³No: 否 — 某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

¹ Mandatory: 필수 — 고객 셀프 수리가 의무 사항인 필수 부품. 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.

² Optional: 옵션 — 고객 셀프 수리가 선택 사항인 부품. 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

³ No: No — 고객 셀프 수리가 불가능하도록 설계된 HP 부품. 이 부품들은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 고객 보증을 만족시키기 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다.

System components



Item	Description	Spare part number	Customer self repair (on page 6)
7	Optical drives	—	—
	a) SATA DVD-ROM drive	624591-001	Mandatory ¹
	b) SATA DVD-RW drive*	624592-001	Mandatory ¹
8	Front I/O module	691939-001	Mandatory ¹
9	Eight-bay SFF hot-plug drive cage assembly	686753-001	Mandatory ¹
10	Eight-bay SFF hot-plug drive backplane	686759-001	Mandatory ¹
11	Four-bay LFF hot-plug drive backplane	686756-001	Mandatory ¹
12	Four-bay LFF non-hot-plug drive bracket	686746-001	Mandatory ¹
13	Storage drives	—	—
	LFF drives (8.89 cm, 3.5 in)	—	—
	Non-hot-plug drives, SATA	—	—
	a) 500 GB, 6G hard drive	659571-001	Mandatory ¹
	b) 1 TB, 6G hard drive*	659569-001	Mandatory ¹
	c) 2 TB, 6G hard drive*	659570-001	Mandatory ¹

Item	Description	Spare part number	Customer self repair (on page 6)
	d) 3 TB, 6G hard drive*	628183-001	Mandatory ¹
	Non-hot-plug drives, SAS	—	—
	a) 450 GB, 6G hard drive*	517353-001	Mandatory ¹
	b) 600 GB, 6G hard drive*	517355-001	Mandatory ¹
	Hot-plug drives, SATA	—	—
	a) 100 GB, 3G MLC solid state drive*	653968-001	Mandatory ¹
	b) 200 GB, 3G MLC solid state drive*	653969-001	Mandatory ¹
	c) 400 GB, 3G MLC solid state drive*	653970-001	Mandatory ¹
	d) 500 GB, 6G hard drive*	658103-001	Mandatory ¹
	e) 1 TB, 6G hard drive*	657739-001	Mandatory ¹
	f) 2 TB, 6G hard drive*	658102-001	Mandatory ¹
	g) 3 TB, 6G hard drive*	628182-001	Mandatory ¹
	Hot-plug drives, SAS	—	—
	a) 450 GB, 6G hard drive*	653951-001	Mandatory ¹
	b) 600 GB, 6G hard drive*	653952-001	Mandatory ¹
	c) 1 TB, 6G hard drive*	653947-001	Mandatory ¹
	d) 2 TB, 6G hard drive*	653948-001	Mandatory ¹
	e) 3 TB, 6G hard drive*	653959-001	Mandatory ¹
	SFF drives (6.35 cm, 2.5 in)	—	—
	Hot-plug drives, SATA	—	—
	a) 100 GB, 3G MLC solid state drive*	653965-001	Mandatory ¹
	b) 200 GB, 3G MLC solid state drive*	653966-001	Mandatory ¹
	c) 400 GB, 3G MLC solid state drive*	653967-001	Mandatory ¹
	d) 500 GB, 6G hard drive*	656107-001	Mandatory ¹
	e) 1 TB, 6G hard drive*	656108-001	Mandatory ¹
	Hot-plug drives, SAS	—	—
	a) 146 GB, 6G hard drive*	653950-001	Mandatory ¹
	b) 200 GB, 6G SLC solid state drive*	653961-001	Mandatory ¹
	c) 300 GB, 6G hard drive*	653955-001	Mandatory ¹
	d) 300 GB, 6G hard drive*	653960-001	Mandatory ¹
	e) 400 GB, 6G SLC solid state drive*	653962-001	Mandatory ¹
	f) 450 GB, 6G hard drive*	653956-001	Mandatory ¹
	g) 500 GB, 6G hard drive*	653953-001	Mandatory ¹
	h) 600 GB, 6G hard drive*	653957-001	Mandatory ¹
	i) 800 GB, 6G MLC solid state drive*	653964-001	Mandatory ¹

Item	Description	Spare part number	Customer self repair (on page 6)
	j) 900 GB, 6G hard drive*	653971-001	Mandatory ¹
	k) 1 TB, 6G hard drive*	653954-001	Mandatory ¹
14	Front system fan (80 x 38 mm)	686749-001	Mandatory ¹
15	System board assembly (includes alcohol pad and thermal compound)	686757-001	Optional ²
16	Processors (includes alcohol pad and thermal compound)	—	—
	a) 2.3-GHz Intel Xeon E3-1220LV2 processor, 2C, 3 MB, 17 W	686687-001	Optional ²
	b) 2.5-GHz Intel Celeron G540 processor, 2C, 2 MB, 65 W*	665119-001	Optional ²
	c) 2.6-GHz Intel Celeron G1610 processor, 2C 2 MB 55 W*	715893-001	Optional ²
	d) 2.7-GHz Intel Celeron G1620 processor, 2C 2 MB 55 W*	715894-001	Optional ²
	e) 3.1-GHz Intel Pentium G2020 processor, 2C 3 MB 55 W*	715897-001	Optional ²
	f) 3.1-GHz Intel Pentium G2120 processor, 2C, 3 MB, 65 W*	703516-001	Optional ²
	g) 3.1-GHz Intel Xeon E3-1220V2 processor, 4C, 8 MB, 69 W*	686686-001	Optional ²
	h) 3.2-GHz Intel Pentium G2130 processor, 2C 3 MB 55 W*	715898-001	Optional ²
	i) 3.3-GHz Intel Xeon i3-3220 processor, 2C, 3 MB, 55 W*	701538-001	Optional ²
	j) 3.3-GHz Intel Xeon E3-1230V2 processor, 4C, 8 MB, 69 W*	686685-001	Optional ²
	k) 3.4-GHz Intel Xeon i3-3240 processor, 2C, 3 MB, 55 W*	701537-001	Optional ²
	l) 3.4-GHz Intel Xeon E3-1240V2 processor, 4C, 8 MB, 69 W*	686684-001	Optional ²
	m) 3.5-GHz Intel Xeon E3-1270V2 processor, 4C, 8 MB, 69 W*	686683-001	Optional ²
	n) 3.6-GHz Intel Xeon E3-1280V2 processor, 4C, 8 MB, 69 W*	686682-001	Optional ²
17	Heatsink	686741-001	Optional ²
18	DIMMs	—	—
	a) 2 GB, single-rank x8 PC3-12800E-11	664633-001	Mandatory ¹
	b) 2 GB, single-rank x8 PC3L-10600E-9*	664694-001	Mandatory ¹
	c) 4 GB, dual-rank x8 PC3-12800E-11*	664034-001	Mandatory ¹
	d) 4 GB, dual-rank x8 PC3L-10600E-9*	664695-001	Mandatory ¹
	e) 8 GB, dual-rank x8 PC3-12800E-11*	684035-001	Mandatory ¹
	f) 8 GB, dual-rank x8 PC3L-10600E-9*	664696-001	Mandatory ¹
19	Rear system fan (92 x 32 mm)	686748-001	Mandatory ¹
20	Dedicated iLO management port module	686742-001	Mandatory ¹
21	HP 350 W 4U Integrated Power Supply Kit	686761-001	Mandatory ¹

Item	Description	Spare part number	Customer self repair (on page 6)
22	HP 460 W CS Gold Hot Plug Power Supply Kit (92% efficiency)	511777-001	Mandatory ¹
23	RPS backplane module	686744-001	Mandatory ¹
	Cables	—	—
24	8-pin to 4-pin power adapter cable*	686755-001	Mandatory ¹
25	500-mm Mini-SAS cable*	647756-001	Mandatory ¹
26	Mini-SAS to SATA cable assembly (for LFF drive cage)*	686747-001	Mandatory ¹

* Not shown

¹Mandatory—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.

²Optional—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

³No—Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

¹Mandatory: Obligatoire—Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

²Optional: Facultatif—Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

³No: Non—Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

¹Mandatory: Obbligatorie—Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

²Optional: Opzionali—Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese aggiuntive a seconda del tipo di garanzia previsto per il prodotto.

³No: Non CSR—Alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

¹Mandatory: Zwingend—Teile, die im Rahmen des Customer Self Repair Programms ersetzt werden müssen. Wenn Sie diese Teile von HP ersetzen lassen, werden Ihnen die Versand- und Arbeitskosten für diesen Service berechnet.

²Optional: Optional—Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

³No: Kein—Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

¹Mandatory: Obligatorio—componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.

²Optional: Opcional—componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su

sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

³No: No—Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra “No” en el catálogo ilustrado de componentes.

¹Mandatory: Verplicht—Onderdelen waarvoor Customer Self Repair verplicht is. Als u HP verzoekt deze onderdelen te vervangen, komen de reiskosten en het arbeidsloon voor uw rekening.

²Optional: Optioneel—Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garantieservice voor het product.

³No: Nee—Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievooraardelen moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

¹Mandatory: Obrigatória—Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

²Optional: Opcional—Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

³No: Nenhuma—Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca “No” (Não), no catálogo de peças ilustrado.

¹Mandatory : 必須 - 顧客自己修理が必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。

²Optional : 任意 - 顧客自己修理が任意である部品。この部品も顧客自己修理用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、費用を負担していただくことなく保証サービスを受けることができます。

³No : 除外 - HP製品の一部の部品は、顧客自己修理用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品が顧客自己修理除外品である旨が記載されています。

¹Mandatory: 强制性的 — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。

²Optional: 可选的 — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据为您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

³No: 否 — 某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

¹Mandatory: 強制的 — 客戶自行維修所使用的零件是強制的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。

²Optional: 選購的 — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

³No: 否 — 某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

¹ Mandatory: 필수 — 고객 셀프 수리가 의무 사항인 필수 부품. 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.

² Optional: 옵션 — 고객 셀프 수리가 선택 사항인 부품. 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

³ No: No — 고객 셀프 수리가 불가능하도록 설계된 HP 부품. 이 부품들은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 고객 보증을 만족시키기 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다.

Removal and replacement procedures

Required tools

You need the following items for some procedures:

- T-10/T-15 Torx screwdriver (on page [75](#))
- Flathead screwdriver
- HP Insight Diagnostics (on page [62](#))

Safety considerations

Before performing service procedures, review all the safety information.

Preventing electrostatic discharge

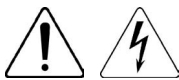
To prevent damaging the system, be aware of the precautions you need to follow when setting up the system or handling parts. A discharge of static electricity from a finger or other conductor may damage system boards or other static-sensitive devices. This type of damage may reduce the life expectancy of the device.

To prevent electrostatic damage:

- Avoid hand contact by transporting and storing products in static-safe containers.
- Keep electrostatic-sensitive parts in their containers until they arrive at static-free workstations.
- Place parts on a grounded surface before removing them from their containers.
- Avoid touching pins, leads, or circuitry.
- Always be properly grounded when touching a static-sensitive component or assembly.

Symbols on equipment

The following symbols may be placed on equipment to indicate the presence of potentially hazardous conditions.



This symbol indicates the presence of hazardous energy circuits or electric shock hazards. Refer all servicing to qualified personnel.

WARNING: To reduce the risk of injury from electric shock hazards, do not open this enclosure. Refer all maintenance, upgrades, and servicing to qualified personnel.



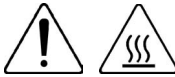
This symbol indicates the presence of electric shock hazards. The area contains no user or field serviceable parts. Do not open for any reason.

WARNING: To reduce the risk of injury from electric shock hazards, do not open this enclosure.



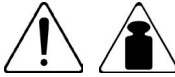
This symbol on an RJ-45 receptacle indicates a network interface connection.

WARNING: To reduce the risk of electric shock, fire, or damage to the equipment, do not plug telephone or telecommunications connectors into this receptacle.



This symbol indicates the presence of a hot surface or hot component. If this surface is contacted, the potential for injury exists.

WARNING: To reduce the risk of injury from a hot component, allow the surface to cool before touching.



This symbol indicates that the component exceeds the recommended weight for one individual to handle safely.

WARNING: To reduce the risk of personal injury or damage to the equipment, observe local occupational health and safety requirements and guidelines for manual material handling.



These symbols, on power supplies or systems, indicate that the equipment is supplied by multiple sources of power.

WARNING: To reduce the risk of injury from electric shock, remove all power cords to completely disconnect power from the system.

Server warnings and cautions



WARNING: This server is very heavy. To reduce the risk of personal injury or damage to the equipment:

- Observe local occupational health and safety requirements and guidelines for manual material handling.
- Get help to lift and stabilize the product during installation or removal, especially when the product is not fastened to the rails. HP recommends that a minimum of two people are required for all rack server installations. A third person may be required to help align the server if the server is installed higher than chest level.
- Use caution when installing the server in or removing the server from the rack; it is unstable when not fastened to the rails.



WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.



WARNING: To reduce the risk of personal injury, electric shock, or damage to the equipment, remove the power cord to remove power from the server. The front panel Power On/Standby button does not completely shut off system power. Portions of the power supply and some internal circuitry remain active until AC power is removed.



CAUTION: Protect the server from power fluctuations and temporary interruptions with a regulating uninterruptible power supply. This device protects the hardware from damage caused by power surges and voltage spikes and keeps the system in operation during a power failure.



CAUTION: Do not operate the server for long periods with the access panel open or removed. Operating the server in this manner results in improper airflow and improper cooling that can lead to thermal damage.

Preparation procedures

To access some components and perform certain service procedures, perform one or more of the following procedures:

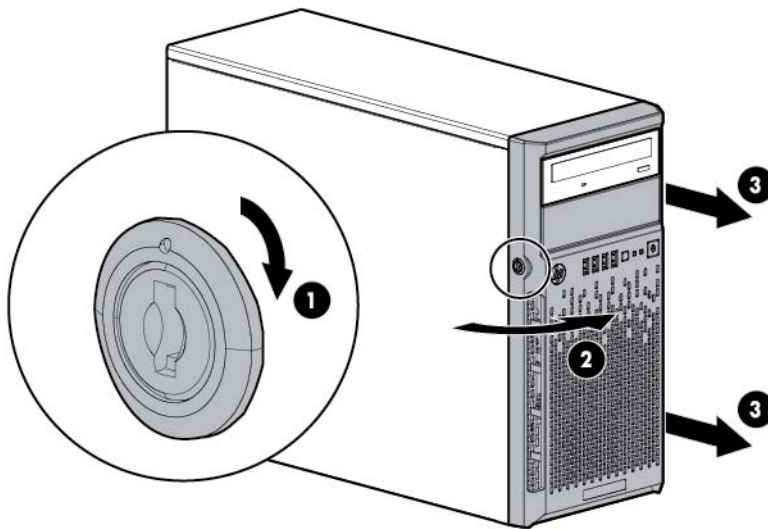
- Unlock the tower bezel.
- Remove the tower bezel (on page 26).
- Power down the server (on page 26).

Before removing the server from a rack or a non-hot-plug component from the server, power down the server.

- Remove the access panel ("Access panel" on page 31).

Remove the tower bezel

1. Unlock and open the tower bezel.
2. Pull the bezel away from the front chassis.



Power down the server

Before powering down the server for any upgrade or maintenance procedures, perform a backup of critical server data and programs.



WARNING: To reduce the risk of personal injury, electric shock, or damage to the equipment, remove the power cord to remove power from the server. The front panel Power On/Standby button does not completely shut off system power. Portions of the power supply and some internal circuitry remain active until AC power is removed.



IMPORTANT: When the server is in standby mode, auxiliary power is still being provided to the system.

To power down the server, use one of the following methods:

- Press and release the Power On/Standby button.
This method initiates a controlled shutdown of applications and the OS before the server enters standby mode.
- Press and hold the Power On/Standby button for more than 4 seconds to force the server to enter standby mode.
This method forces the server to enter standby mode without properly exiting applications and the OS. If an application stops responding, you can use this method to force a shutdown.
- Use a virtual power button selection through iLO.
This method initiates a controlled remote shutdown of applications and the OS before the server enters standby mode.

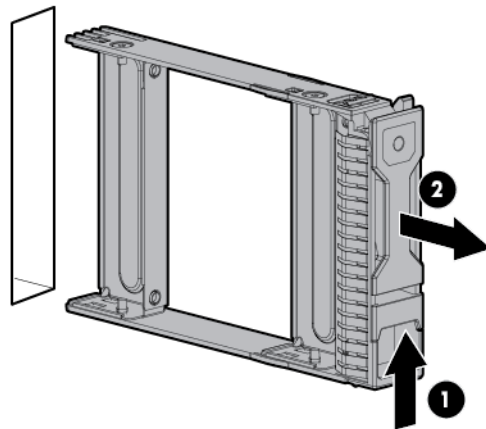
Before proceeding, verify the server is in standby mode by observing that the system power LED is amber.

Drive blank or carrier

CAUTION: To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

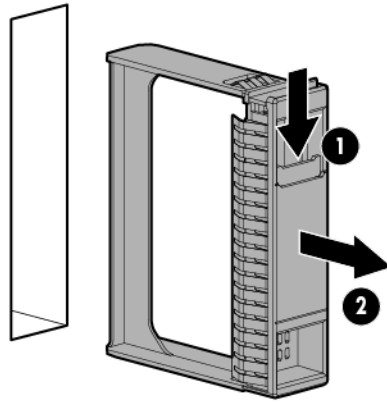
To remove the component:

1. Unlock and open the tower bezel.
2. Do one of the following:
 - In a non-hot-plug drive configuration, remove the drive carrier.



To replace the drive carrier, slide the component into the bay until it clicks.

- In a hot-plug drive configuration, remove the drive blank.



To replace the LFF drive blank, slide the component into the bay until it clicks.

To replace the SFF drive blank, while pressing the release latch, slide the component into the bay until it is fully seated.

Storage drive

Non-hot-plug drive

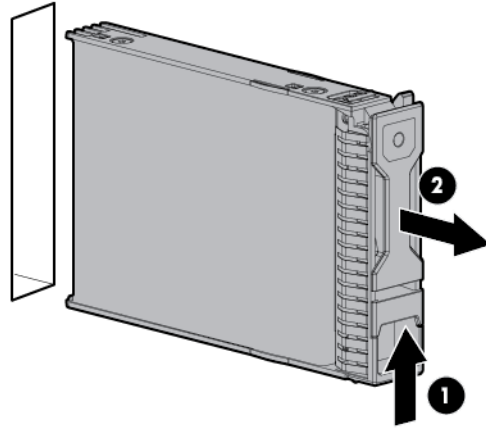


CAUTION: To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

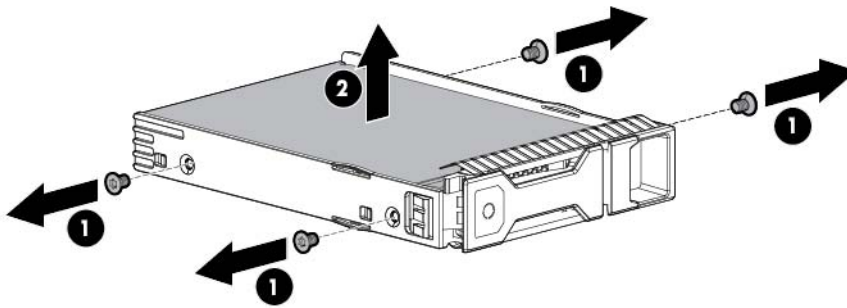
To remove the component:

1. Back up all server data on the drive.
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Unlock and open the tower bezel.

5. Remove the drive.



6. Remove the drive from the carrier.



To replace the component, reverse the removal procedure.

Hot-plug drive

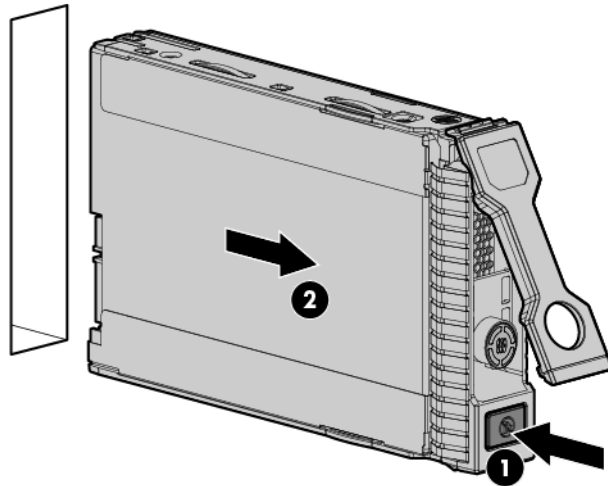


CAUTION: To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

To remove the component:

1. Back up all server data on the drive.
2. Determine the status of the drive from the drive LED definitions ("[Hot-plug drive LED definitions](#)" on page 73).
3. Unlock and open the tower bezel.

4. Remove the drive.



To replace the component, reverse the removal procedure.

Hot-plug power supply

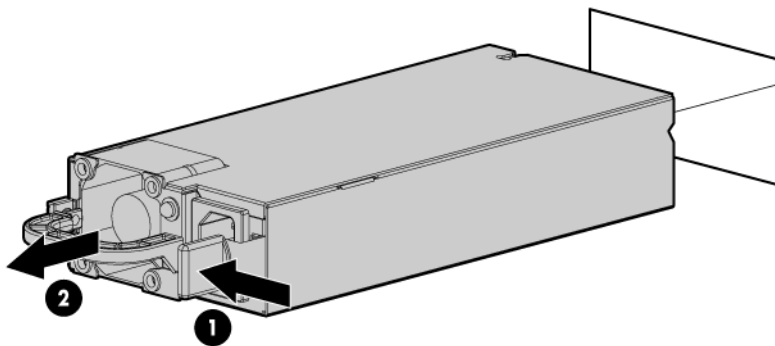
CAUTION: To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

To remove the component:

1. Power down the server (on page 26).

WARNING: To reduce the risk of personal injury from hot surfaces, allow the power supply or power supply blank to cool before touching it.

2. Remove the power supply.



Power redundancy requires the presence of two power supply modules in the system.



CAUTION: The default and redundant power supplies in the server must have the same output power capacity. Verify that all power supplies have the same part number and label color. The system becomes unstable and might shut down when it detects mismatched power supplies.

To replace the component, reverse the removal procedure.

Access panel

To remove the component:

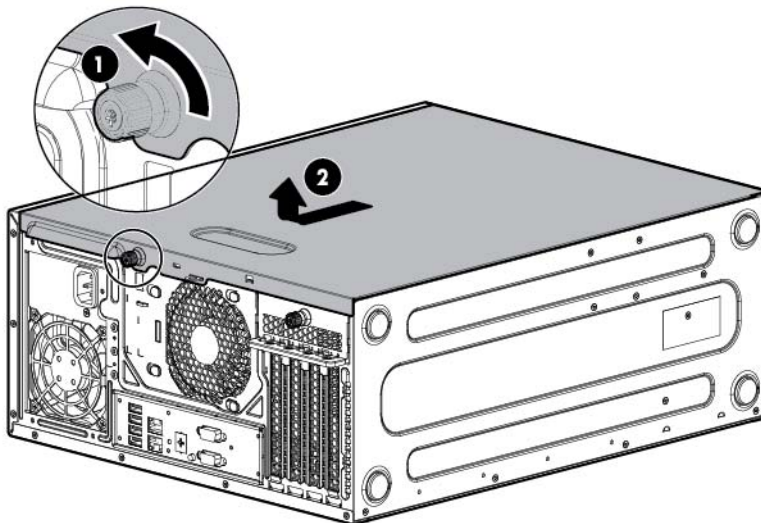


WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.



CAUTION: For proper cooling, do not operate the server without the access panel, baffles, expansion slot covers, or blanks installed. If the server supports hot-plug components, minimize the amount of time the access panel is open.

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Place the server on its side.
5. Remove the access panel:
 - a. Loosen the access panel thumbscrew.
 - b. Slide the access panel back.
 - c. Lift the access panel away from the chassis.



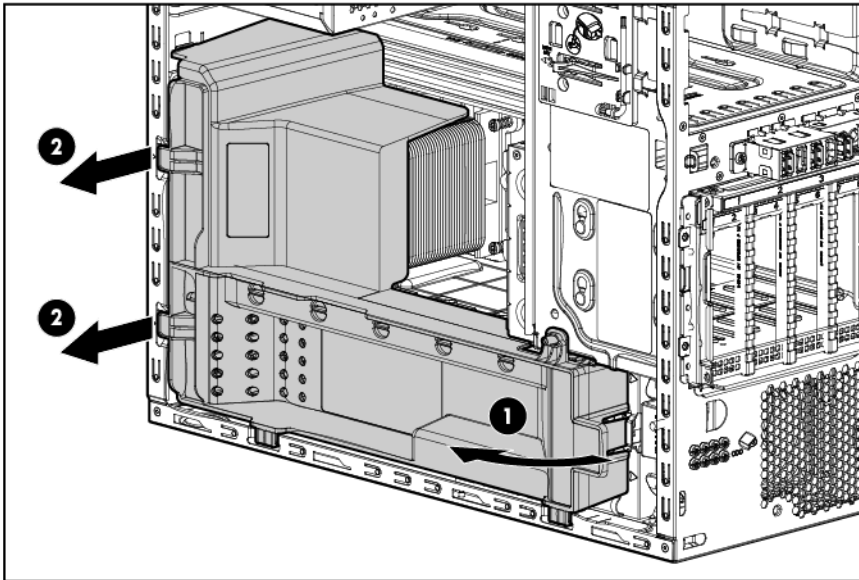
To replace the component, reverse the removal procedure.

Air baffle

To remove the component:

- △ **CAUTION:** For proper cooling, do not operate the server without the access panel, baffles, expansion slot covers, or blanks installed. If the server supports hot-plug components, minimize the amount of time the access panel is open.

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Remove the access panel ("Access panel" on page 31).
5. Remove the air baffle.



To replace the component, reverse the removal procedure.

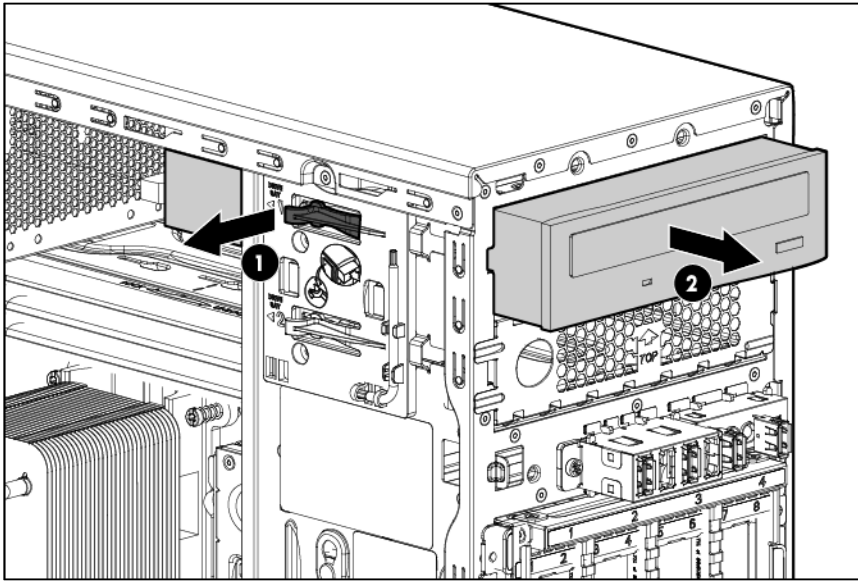
Optical drive

- △ **CAUTION:** To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock and open the tower bezel.
4. Remove the access panel ("Access panel" on page 31).

5. Disconnect the SATA and power cables from the optical drive.
6. Remove the optical drive.



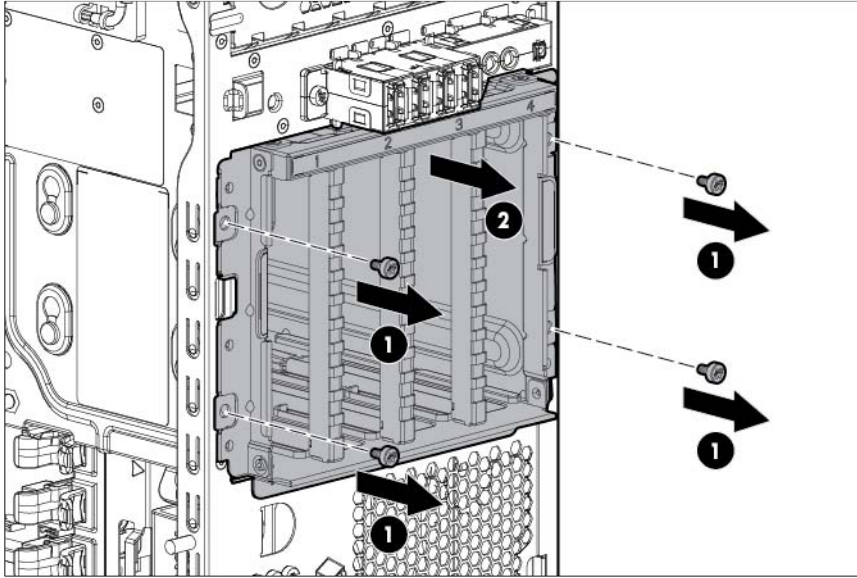
To replace the component, reverse the removal procedure.

Drive cage

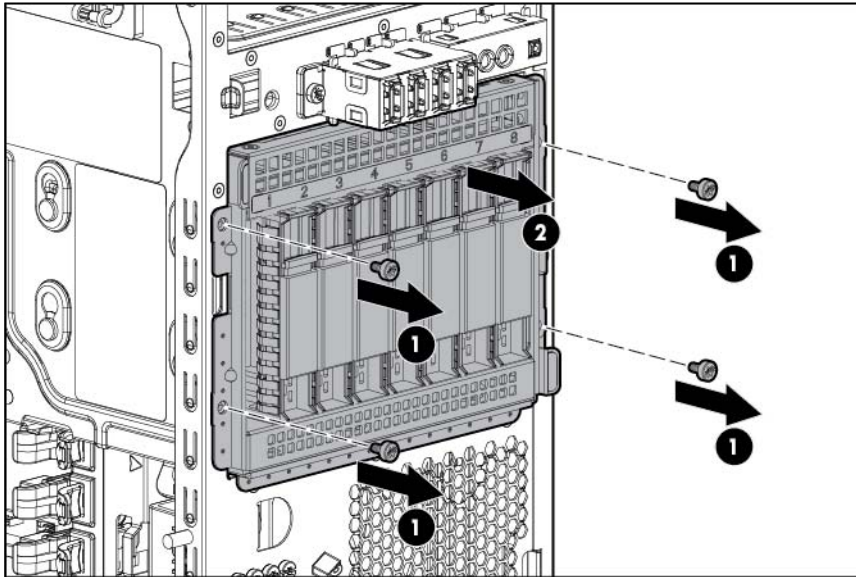
To remove the component:

1. Power down the server (on page [26](#)).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Remove the tower bezel (on page [26](#)).
4. Remove the access panel ("[Access panel](#)" on page [31](#)).
5. If the drives are connected to a storage controller card, remove the air baffle.
6. Remove all installed drives ("[Storage drive](#)" on page [28](#)).
7. Disconnect the drive cage cables:
 - a. Disconnect the Mini-SAS cable from the system board or from the storage controller option.
 - b. Disconnect the drive power cable from the 10-pin power supply connector.
8. Remove the drive cage:

- Four-bay LFF drive cage



- Eight-bay SFF drive cage



To replace the component, reverse the removal procedure.

To convert the four-bay non-hot-plug drive cage to a hot-plug model, remove the cage bracket, and then install the hot-plug backplane option before installing the cage back to the server ("[Drive cage bracket or backplane](#)" on page [34](#)).

Drive cage bracket or backplane

To remove the component:

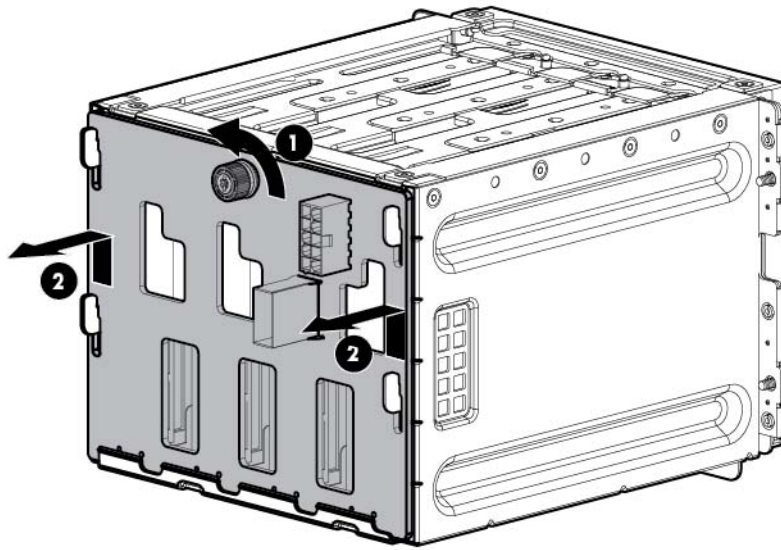
1. Power down the server (on page [26](#)).
2. Remove all power:
 - a. Disconnect each power cord from the power source.

-

- For image clarity, the Mini-SAS and power cables attached to the drive cage are not shown in the following figures.

-

- For a hot-plug drive cage, loosen the backplane thumbscrew, and then remove the backplane assembly from the drive cage.



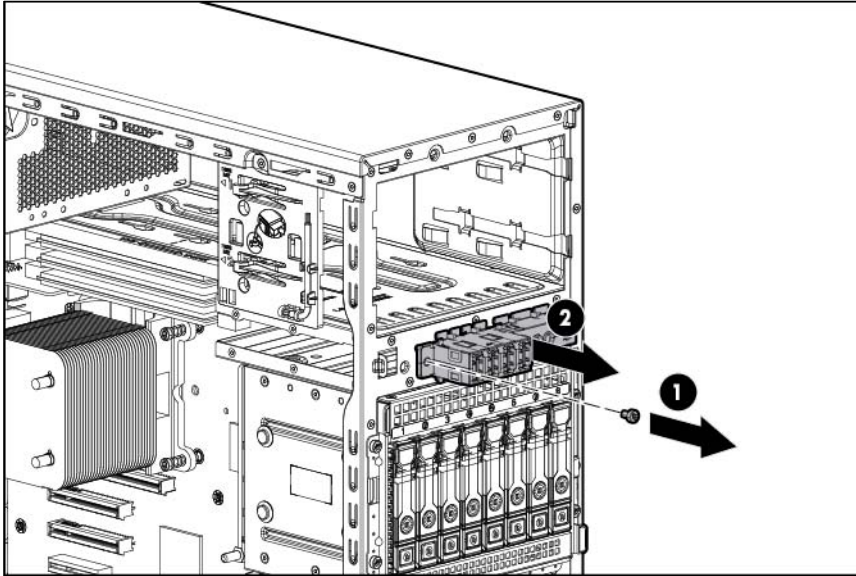
To replace the component, reverse the removal procedure.

Front I/O module

To remove the component:

1. Power down the server (on page [26](#)).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock and open the tower bezel.
4. Remove the access panel ("[Access panel](#)" on page [31](#)).
5. Remove the air baffle ("[Air baffle](#)" on page [32](#)).
6. Disconnect the front USB and LED cables from the system board ("[Front panel cabling](#)" on page [76](#)).

7. Remove the front I/O module.



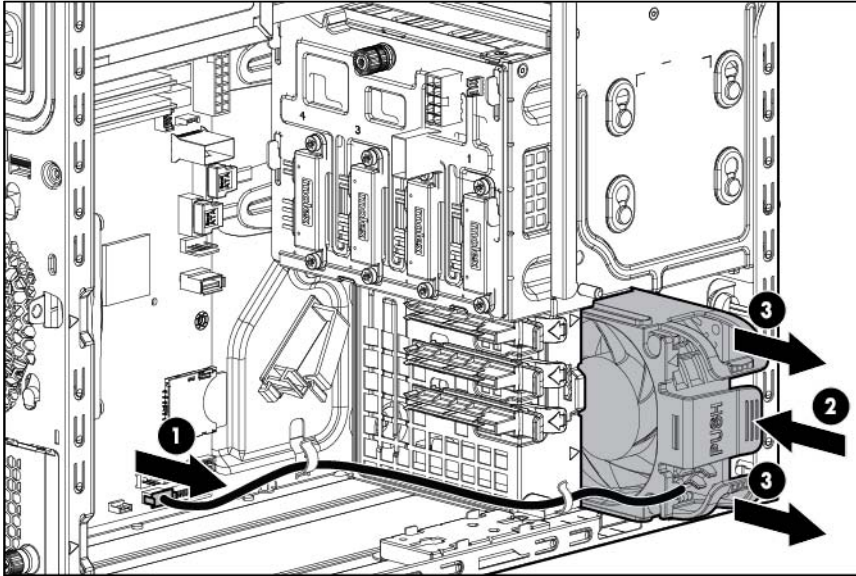
To replace the component, reverse the removal procedure.

Front system fan

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Remove the access panel ("Access panel" on page 31).
5. Remove the air baffle ("Air baffle" on page 32).
6. Disconnect the fan cable.

7. Press the release latch, and then remove the fan module.



To replace the component, reverse the removal procedure.

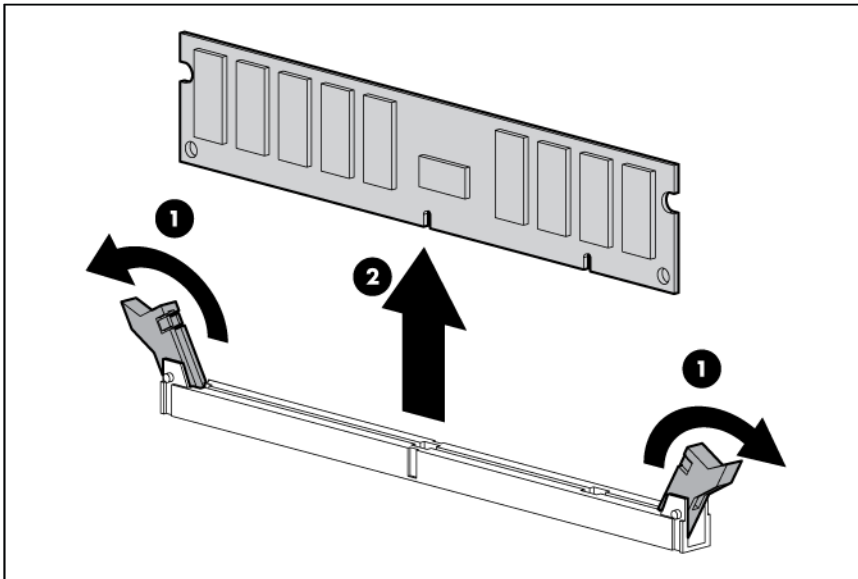
DIMMs

General DIMM slot population guidelines

- The server has four memory slots.
- The server supports two channels with two DIMM slots per channel.
 - Memory channel 1 consists of the two DIMMs that are closest to the processor.
 - Memory channel 2 consists of the two DIMMs that are farthest from the processor.
- White DIMM slot indicates the first slot of a channel (2-A, 4-B).
- Memory speed support depends on the type of processor installed. See the technical specification of the installed processor for more information.
- The server supports up to 1600 MT/s ECC UDIMMs.
- The server supports up to 32 GB (4x8 GB) UDIMMs.
- The server does not support:
 - RDIMMs
 - Non-ECC UDIMMs
 - Elpida DIMMs
- When installing DIMMs:
 - Populate the DIMM slots in this sequence: 2-A, 4-B, 1-C, 3-D.
 - Use HP-qualified UDIMMs.

Removing a DIMM

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Remove the access panel ("Access panel" on page 31).
5. Remove the air baffle ("Air baffle" on page 32).
6. Open the DIMM slot latches.
7. Remove the DIMM.



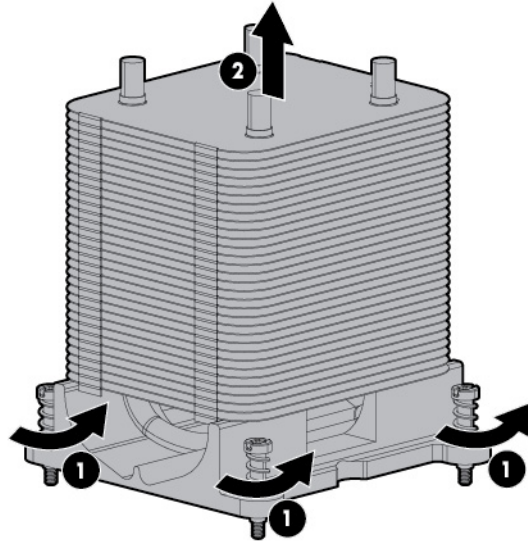
To replace the component, reverse the removal procedure.

Heatsink

To remove the component:

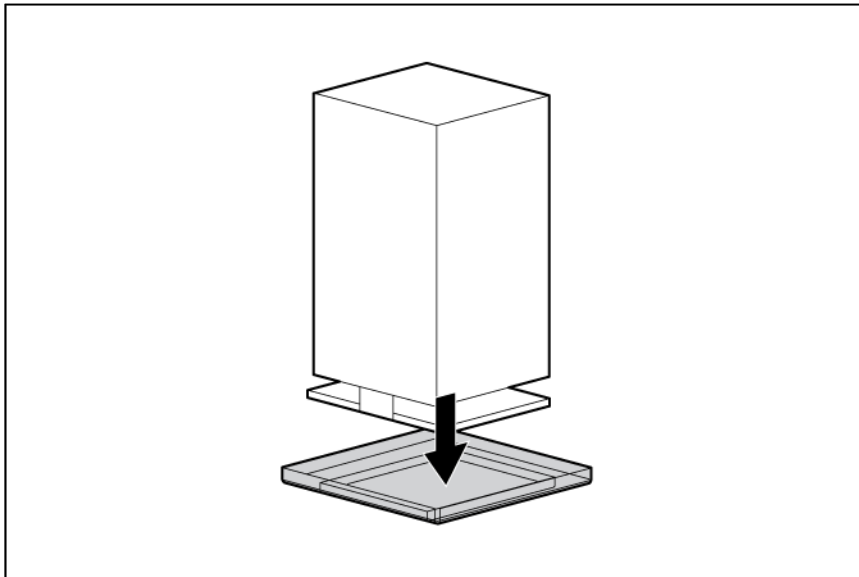
1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Remove the access panel ("Access panel" on page 31).
5. Remove the air baffle ("Air baffle" on page 32).
6. Remove the heatsink:
 - a. Loosen one pair of diagonally opposite screws halfway, and then loosen the other pair of screws.
 - b. Completely loosen all screws in the same sequence.

- c. Remove the heatsink from the processor backplate.



To replace the component:

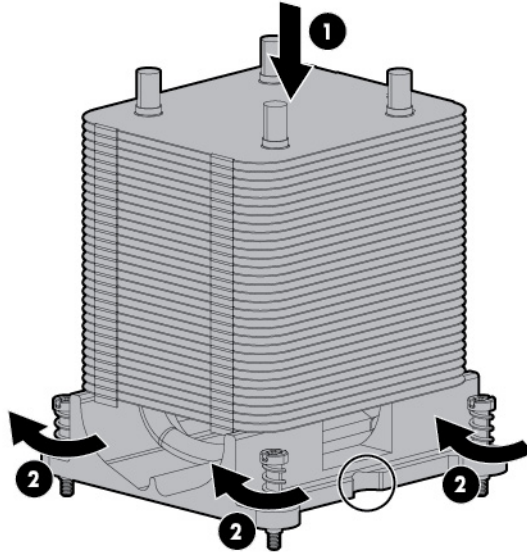
1. Clean the old thermal grease from the processor with the alcohol swab. Allow the alcohol to evaporate before continuing.
2. Remove the thermal interface protective cover from the heatsink.



CAUTION: Do not overtighten the screws as this might damage the board, connectors, or screws and voids the warranty of the board.

3. Install the heatsink:
 - a. Position the heatsink using the guide pin on the processor backplate.
 - b. Tighten one pair of diagonally opposite screws halfway, and then tighten the other pair of screws.

- c. Finish the installation by completely tightening the screws in the same sequence.



4. Install the air baffle ("[Air baffle](#)" on page 32).
5. Install the access panel.
6. Lock the tower bezel.
7. Connect each power cord to the server.
8. Connect each power cord to the power source.
9. Press the Power On/Standby button.

The server exits standby mode and applies full power to the system. The system power LED changes from amber to green.

Processor



WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.



CAUTION: To avoid damage to the processor and system board, only authorized personnel should attempt to replace or install the processor in this server.



IMPORTANT: If installing a processor with a faster speed, update the system ROM before installing the processor.

To remove the component:

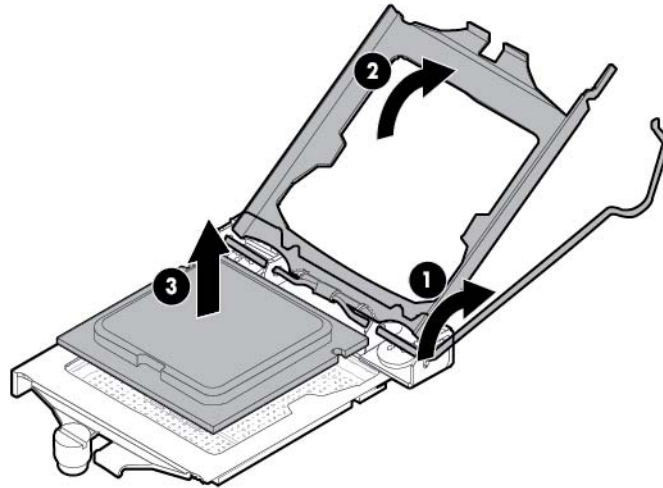
1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Remove the access panel ("[Access panel](#)" on page 31).

5. Remove the air baffle ("Air baffle" on page 32).
6. Remove the heatsink ("Heatsink" on page 39).

△ **CAUTION:** To avoid damage to the processor, do not touch the bottom of the processor, especially the contact area.

△ **CAUTION:** The pins on the processor socket are very fragile. Any damage to them may require replacing the system board.

7. Open the processor locking lever, and then open the processor retaining bracket.
8. Grasp the processor by the edges, and then lift it out of the socket.



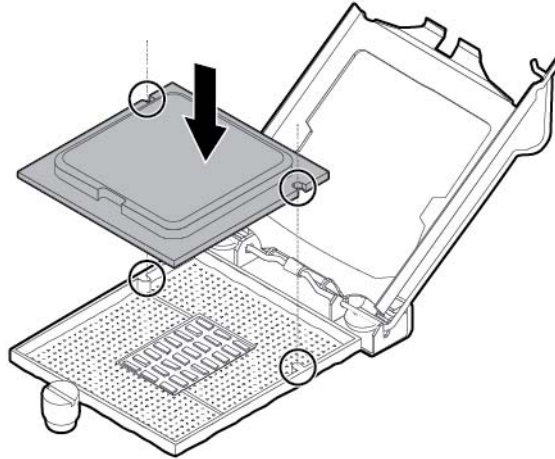
To replace the component:

△ **CAUTION:** Failure to completely open the processor locking lever prevents the processor from seating during installation, leading to hardware damage.

△ **CAUTION: THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED.** To avoid damage to the system board:

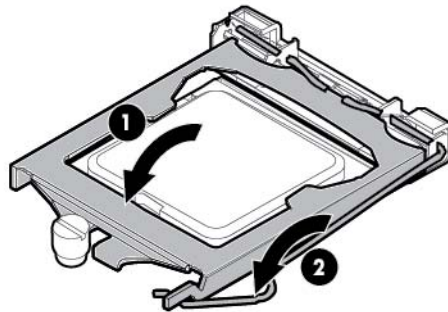
- Do not touch the processor socket contacts.
- Do not tilt or slide the processor when lowering the processor into the socket.

1. Install the processor. Use the notches on both sides of the processor to properly align it into the socket.

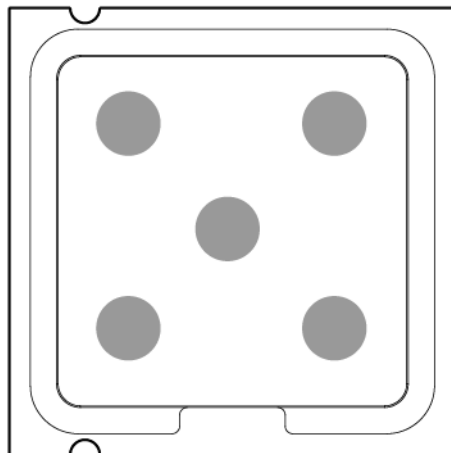


CAUTION: Be sure to close the processor socket retaining bracket before closing the processor locking lever. The lever should close without resistance. Forcing the lever closed can damage the processor and socket, requiring system board replacement.

2. Close the processor retaining bracket, and then secure the processor locking lever.



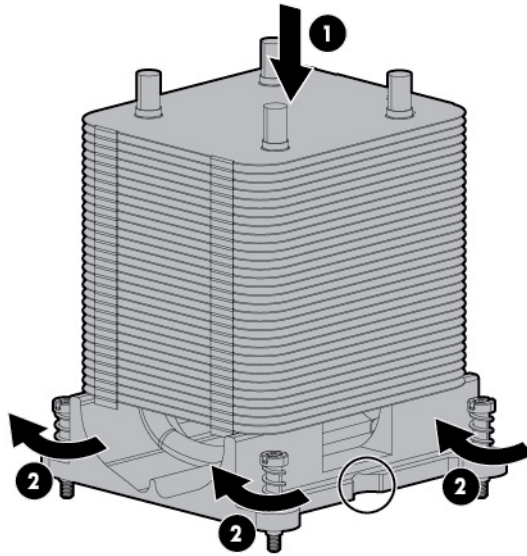
3. Clean the old thermal grease from the heatsink with the alcohol swab. Allow the alcohol to evaporate before continuing.
4. Apply all the grease to the top of the processor in the following pattern to ensure even distribution.





CAUTION: Do not overtighten the screws as this might damage the board, connectors, or screws and voids the warranty of the board.

5. Install the heatsink:
 - a. Position the heatsink using the guide pin on the processor backplate.
 - b. Tighten one pair of diagonally opposite screws halfway, and then tighten the other pair of screws.
 - c. Finish the installation by completely tightening the screws in the same sequence.



6. Install the air baffle.
7. Install the access panel.
8. Lock the tower bezel.
9. Connect each power cord to the server.
10. Connect each power cord to the power source.
11. Press the Power On/Standby button.

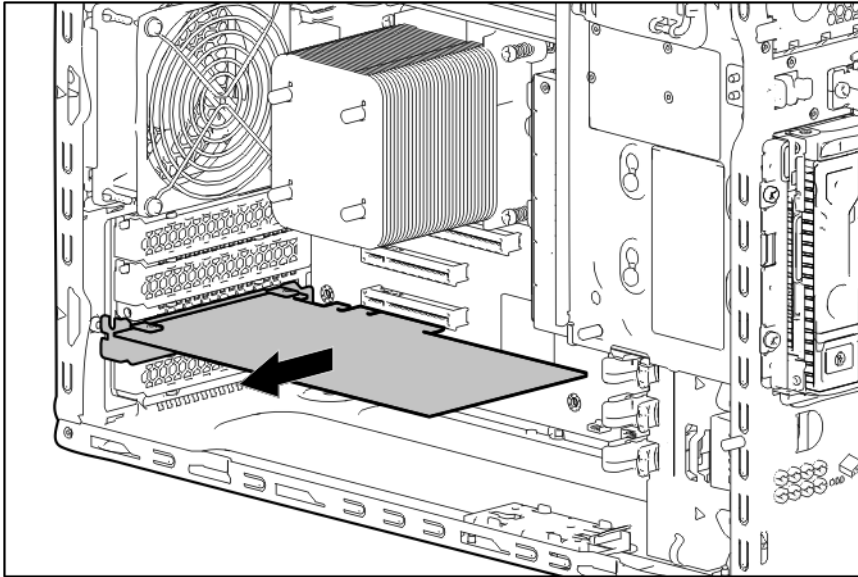
The server exits standby mode and applies full power to the system. The system power LED changes from amber to green.

Expansion board

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Remove the access panel ("[Access panel](#)" on page 31).
5. Remove the air baffle ("[Air baffle](#)" on page 32).
6. Disconnect all cables connected to the expansion board.

7. Remove the expansion slot cover retainer.
8. If removing a full-length expansion board, remove the board retainer securing it.
9. Remove the expansion board.



To replace the component, reverse the removal procedure.

Flash-backed write cache procedures

The following types of procedures are provided for the FBWC option:

- Removal and replacement of failed components:
 - Removing the cache module ("[FBWC module](#)" on page 45)
 - Removing the capacitor pack ("[Capacitor pack](#)" on page 46)
- Recovery of cached data from a failed server ("[Recovering data from the flash-backed write cache](#)" on page 48)

△ **CAUTION:** Do not detach the cable that connects the battery pack or capacitor pack to the cache module. Detaching the cable causes any unsaved data in the cache module to be lost.

FBWC module

△ **CAUTION:** The cache module connector does not use the industry-standard DDR3 mini-DIMMs. Do not use the controller with cache modules designed for other controller models, because the controller can malfunction and you can lose data. Also, do not transfer this cache module to an unsupported controller model, because you can lose data.

△ **CAUTION:** In systems that use external data storage, be sure that the server is the first unit to be powered down and the last to be powered back up. Taking this precaution ensures that the system does not erroneously mark the drives as failed when the server is powered up.

To remove the component:

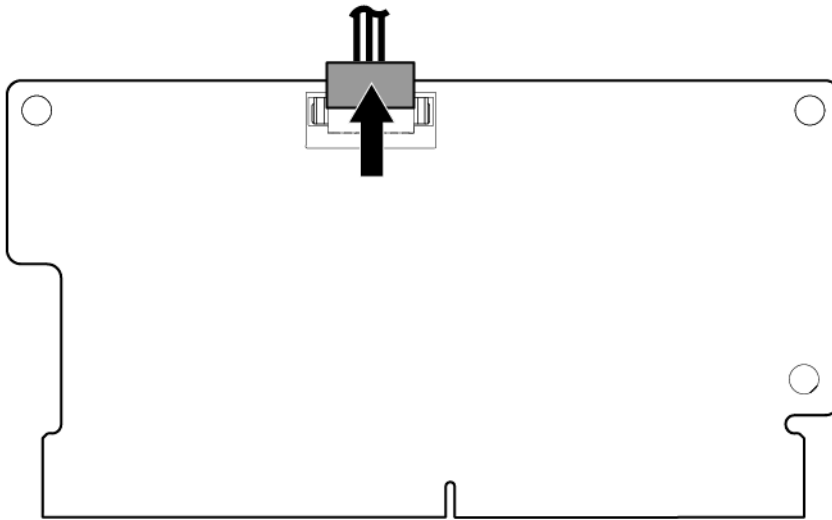
1. Power down the server (on page 26).

2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock and open the tower bezel.
4. Remove the access panel ("[Access panel](#)" on page 31).
5. Remove the air baffle ("[Air baffle](#)" on page 32).

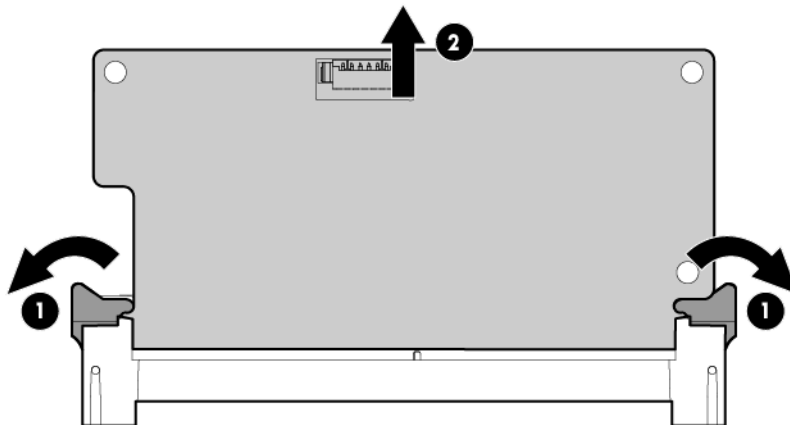


CAUTION: When connecting or disconnecting the capacitor pack cable, the connectors on the cache module and cable are susceptible to damage. Avoid excessive force and use caution to avoid damage to these connectors.

6. Disconnect the capacitor pack cable from the cache module.



7. Remove the cache module.



To replace the component, reverse the removal procedure.

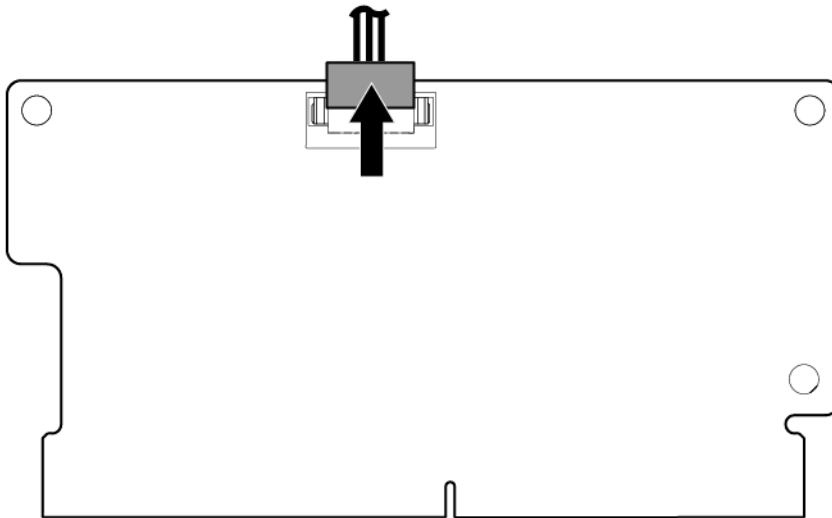
Capacitor pack



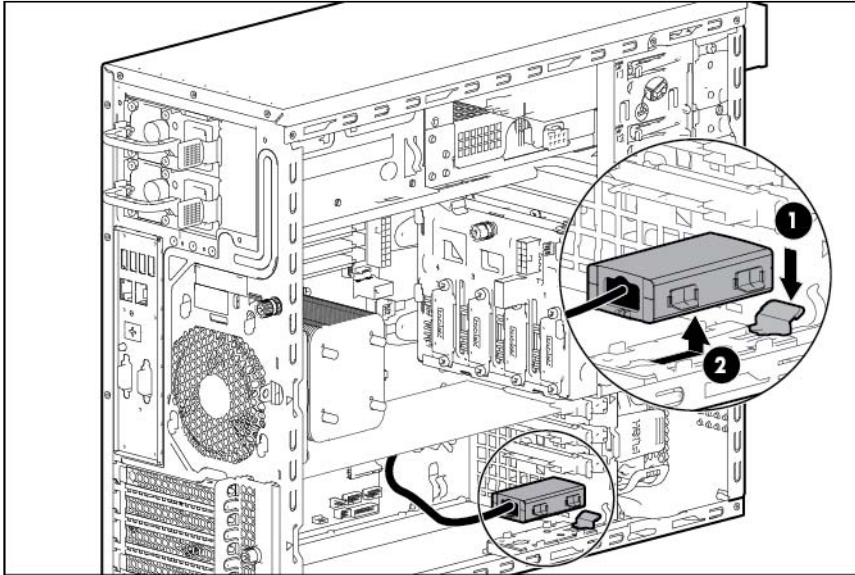
CAUTION: In systems that use external data storage, be sure that the server is the first unit to be powered down and the last to be powered back up. Taking this precaution ensures that the system does not erroneously mark the drives as failed when the server is powered up.

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Remove the access panel ("[Access panel](#)" on page 31).
5. Remove the air baffle ("[Air baffle](#)" on page 32).
6. If the existing cache module is connected to a capacitor pack, observe the FBWC module LEDs:
 - If a backup is in progress, wait for the backup to complete.
 - If the backup is complete, or if the cache has failed, remove the controller from the server, and then continue with the next step.
7. Disconnect the capacitor pack cable from the cache module.



8. Remove the capacitor pack.



To replace the component, reverse the removal procedure.

Recovering data from the flash-backed write cache

If the server fails, use the following procedure to recover data temporarily stored in the FBWC.



CAUTION: Before starting this procedure, read the information about protecting against electrostatic discharge ("[Preventing electrostatic discharge](#)" on page 24).

1. Perform one of the following:
 - Set up a recovery server using an identical server model. Do not install any internal drives or FBWC in this server. (HP recommends this option.)
 - Find a server that has enough empty drive bays to accommodate all the drives from the failed server and that meets all the other requirements for drive and array migration.
2. Power down the failed server ("[Power down the server](#)" on page 26).
3. Transfer the drives from the failed server to the recovery server.
4. Perform one of the following:
 - If the array controller has failed, remove the cache module and capacitor pack from the failed array controller, and install the cache module and capacitor pack on an identical array controller model in the recovery server.
 - If the server has failed, remove the controller, cache module, and capacitor pack from the failed server, and install the controller, cache module, and capacitor pack in the recovery server.
5. Power up the recovery server. If there was data in the cache at the time of the controller or server failure, a 1792 POST message appears, stating that valid data was flushed from the cache. This data is now stored on the drives in the recovery server. You can now transfer the drives (and controller, if one is used) to another server.

If the drives are migrated to different drive positions or there are volumes present in the recovery server, a 1724 POST message appears, stating that logical drive configuration has been updated automatically.

System battery

If the server no longer automatically displays the correct date and time, then replace the battery that provides power to the real-time clock. Under normal use, battery life is 5 to 10 years.

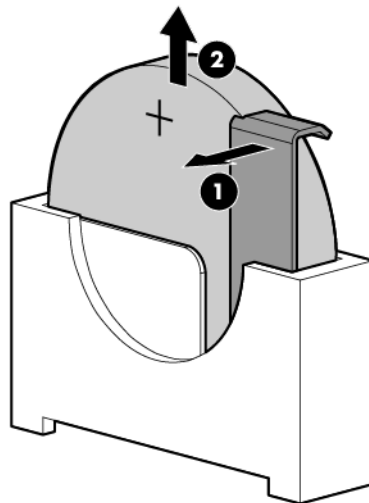


WARNING: The computer contains an internal lithium manganese dioxide, a vanadium pentoxide, or an alkaline battery pack. A risk of fire and burns exists if the battery pack is not properly handled. To reduce the risk of personal injury:

- Do not attempt to recharge the battery.
- Do not expose the battery to temperatures higher than 60°C (140°F).
- Do not disassemble, crush, puncture, short external contacts, or dispose of in fire or water.
- Replace only with the spare designated for this product.

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Remove the access panel ("[Access panel](#)" on page 31).
5. Locate the battery on the system board ("[System board components](#)" on page 69).
6. Remove the battery.



IMPORTANT: Replacing the system board battery resets the system ROM to its default configuration. After replacing the battery, reconfigure the system through RBSU.

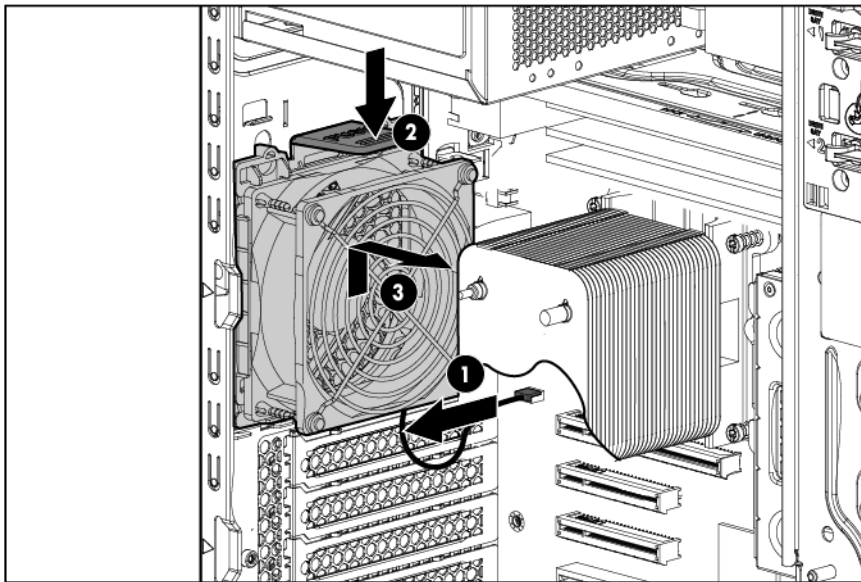
To replace the component, reverse the removal procedure.

For more information about battery replacement or proper disposal, contact an authorized reseller or an authorized service provider.

Rear system fan

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Remove the access panel ("Access panel" on page 31).
5. Remove the air baffle ("Air baffle" on page 32).
6. Remove any existing expansion board that blocks access to the rear system fan connector.
7. Disconnect the fan cable.
8. Press and hold the fan latch, and then remove the fan.



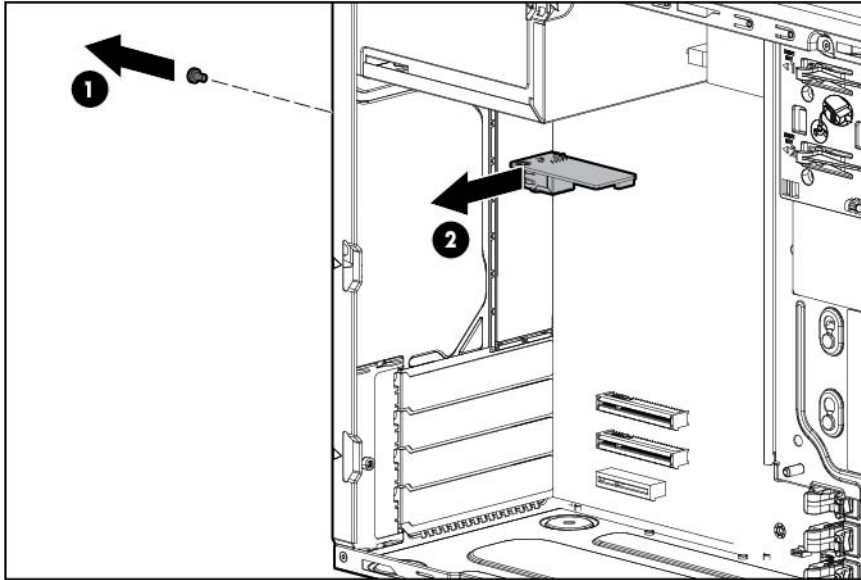
To replace the component, reverse the removal procedure.

Dedicated iLO management port

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Remove the access panel ("Access panel" on page 31).
5. Remove the air baffle ("Air baffle" on page 32).
6. Remove the rear system fan ("Rear system fan" on page 50).

7. Remove the iLO module from the chassis.



To replace the component, reverse the removal procedure.

Enabling the dedicated iLO management port

The onboard NIC 1/shared iLO connector is set as the default system iLO port.

To enable the installed dedicated iLO module:

1. During the server startup sequence after module installation, to access iLO RBSU, press the **F8** key.
2. Select the **Network** menu.
3. Click the **Network Interface Adapter** field.
4. To change the setting to **ON**, press the spacebar.
5. To save the new settings, press the **F10** key.
6. Select the **File** menu, and then to close iLO RBSU, click **Exit**.
7. To confirm exiting iLO RBSU, click **OK**. The server automatically reboots.



IMPORTANT: If the iLO RBSU settings are reset to the default values, access to the machine will be lost. Access the physical machine, and then set the **Network Interface Adapter** field to **ON**.

Non-hot-plug power supply

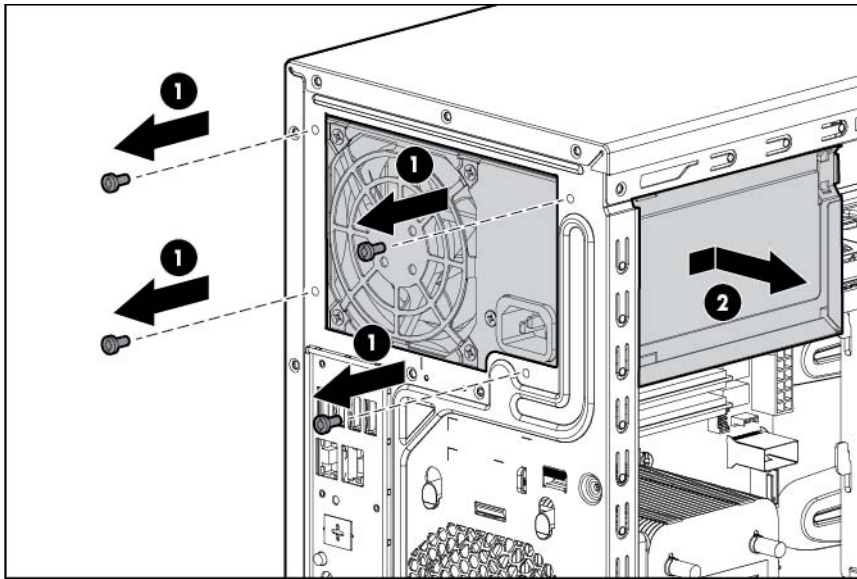
To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Remove the access panel ("Access panel" on page 31).



WARNING: To reduce the risk of personal injury from hot surfaces, allow the power supply or power supply blank to cool before touching it.

5. Disconnect the power supply cables from the drive cage and the system board.
6. Remove the power supply.



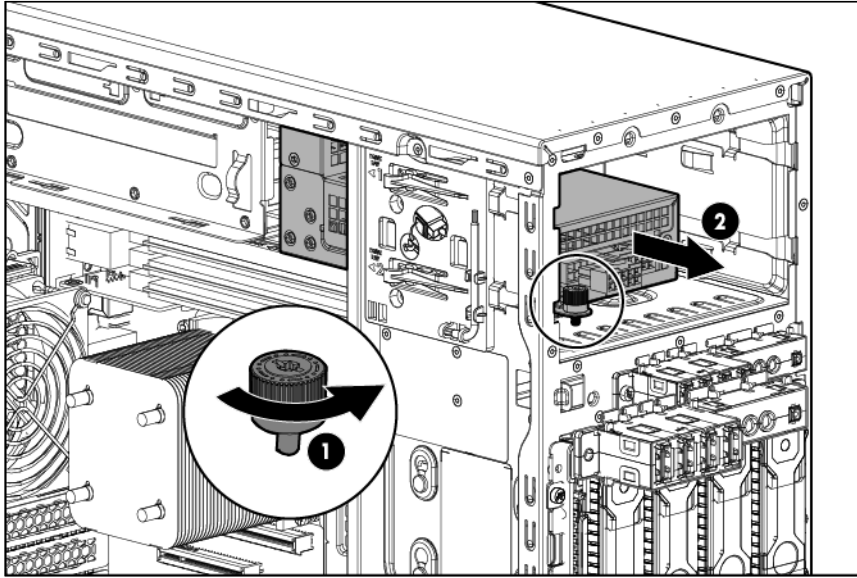
To replace the component, reverse the removal procedure.

RPS backplane module

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock and open the tower bezel.
4. Remove the access panel ("Access panel" on page 31).
5. Remove the EMI shield from the lower media bay.
6. Remove the optical drive from the upper media bay ("Optical drive" on page 32).
7. Disconnect the power supply cables from the drive cage and the system board.

8. Remove the RPS backplane module.



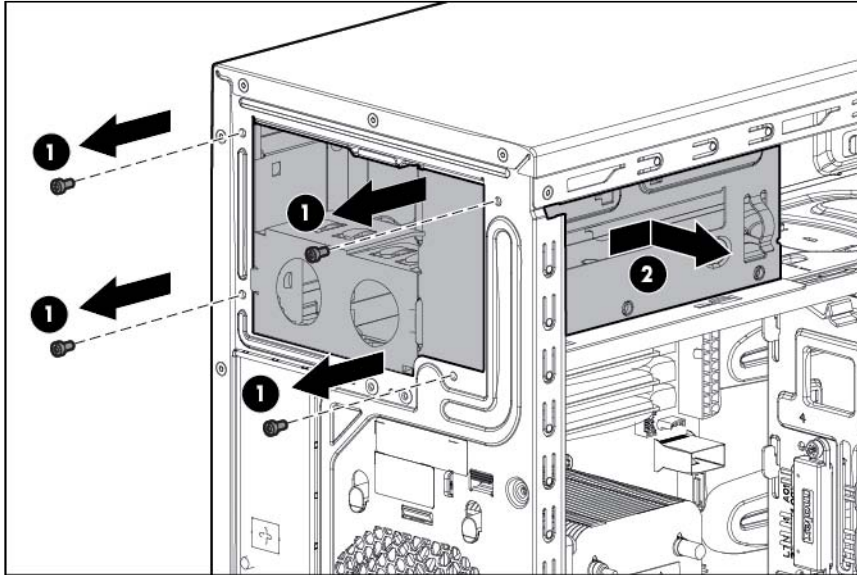
To replace the component, reverse the removal procedure.

RPS cage

To remove the component:

1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Remove the access panel ("Access panel" on page 31).
5. Remove the air baffle ("Air baffle" on page 32).
6. Disconnect the power supply cables from the system board and the drives.
7. Remove the EMI shield from the lower media bay.
8. Remove the optical drive from the upper media bay ("Optical drive" on page 32).
9. Remove the hot-plug power supplies ("Hot-plug power supply" on page 30).
10. Remove the RPS backplane module ("RPS backplane module" on page 52).

11. Remove the power supply cage.



To replace the component, reverse the removal procedure.

System board

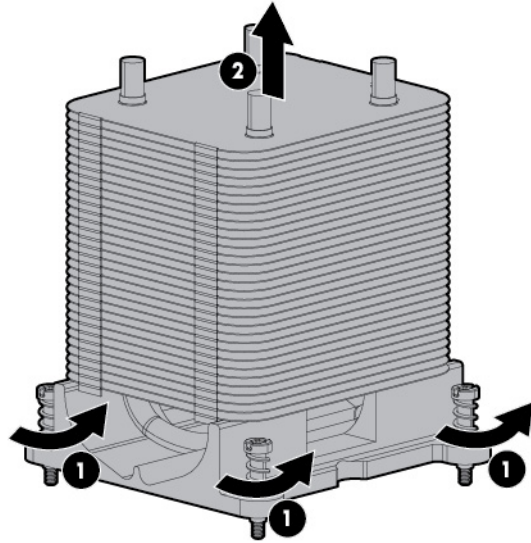


CAUTION: To avoid ESD damage, when removing electrostatic-sensitive components from the failed system board, place the components on a static-dissipating work surface or inside separate antistatic bags.

To remove the system board:

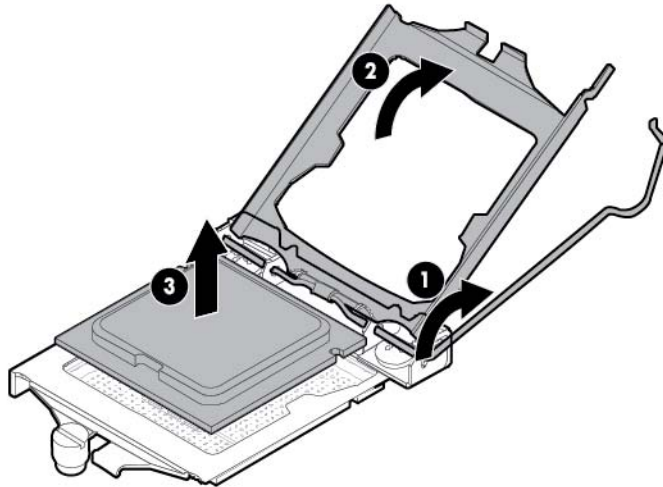
1. Power down the server (on page 26).
2. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
3. Unlock the tower bezel.
4. Remove the access panel ("Access panel" on page 31).
5. Remove the air baffle ("Air baffle" on page 32).
6. Remove the rear system fan ("Rear system fan" on page 50).
7. Remove the capacitor pack ("Capacitor pack" on page 46).
8. Remove the heatsink:
 - a. Loosen one pair of diagonally opposite screws halfway, and then loosen the other pair of screws.
 - b. Completely loosen all screws in the same sequence.

- c. Remove the heatsink from the processor backplate.



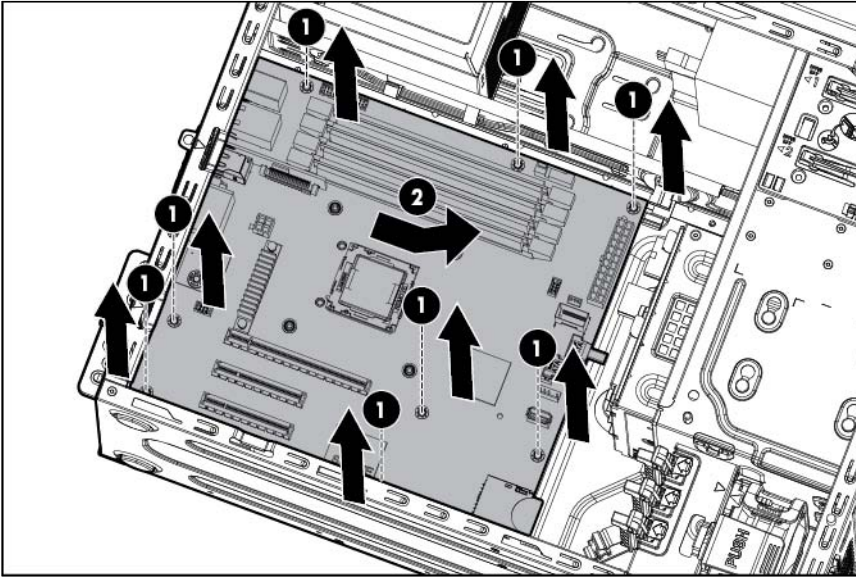
CAUTION: To avoid damage to the processor, do not touch the bottom of the processor, especially the contact area.

- 9. Open the processor locking lever, and then open the processor retaining bracket.
- 10. Grasp the processor by the edges, and then lift it out of the socket.



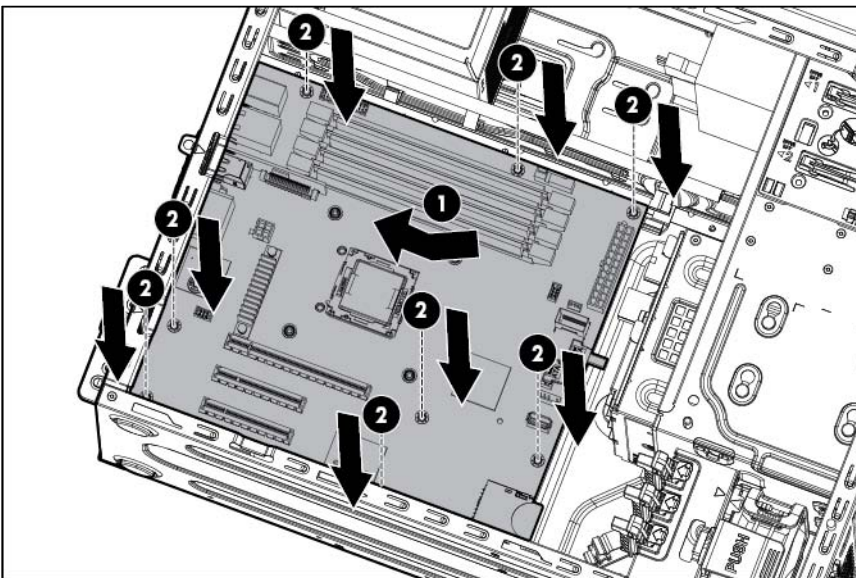
- 11. Remove all DIMMs ("[Removing a DIMM](#)" on page 39).
- 12. Remove all expansion boards ("[Expansion board](#)" on page 44).
- 13. If installed, remove the dedicated iLO module ("[Dedicated iLO management port](#)" on page 50).
- 14. Disconnect all cables connected to the system board.
- 15. Remove the system board:
 - a. Remove the system board screws.

- b. Lift the system board out of the chassis.



To replace the system board:

1. Install the system board.



2. Connect all cables disconnected from the failed system board.
3. Install the DIMMs.
4. If removed, install the dedicated iLO management port.
5. Install the expansion boards.

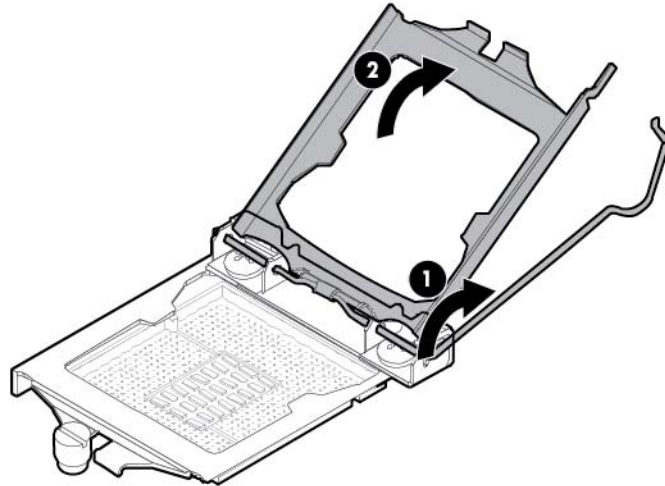


CAUTION: Failure to completely open the processor locking lever prevents the processor from seating during installation, leading to hardware damage.

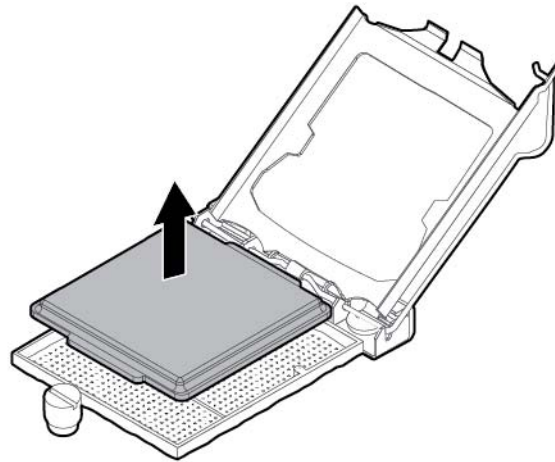


CAUTION: To avoid damage to the processor, do not touch the bottom of the processor, especially the contact area.

6. Open the processor locking lever, and then open the processor retaining bracket.



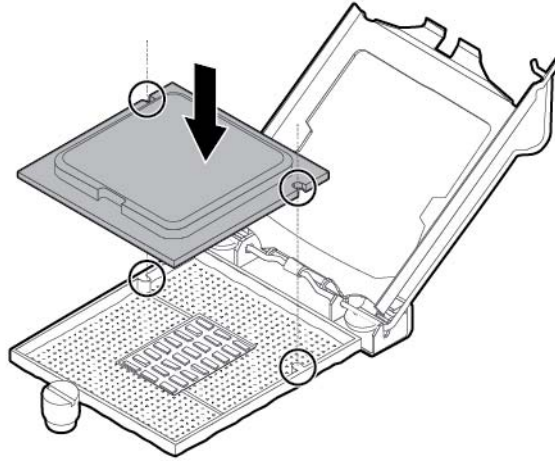
7. Remove the processor socket cover.



CAUTION: THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED. To avoid damage to the system board:

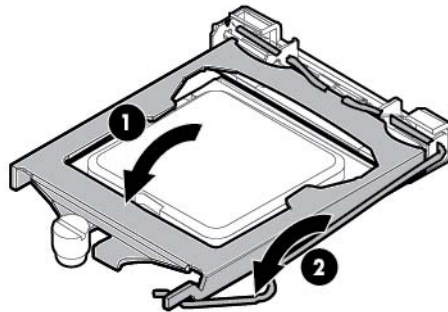
- Do not touch the processor socket contacts.
- Do not tilt or slide the processor when lowering the processor into the socket.

8. Install the processor. Use the notches on both sides of the processor to properly align it into the socket.

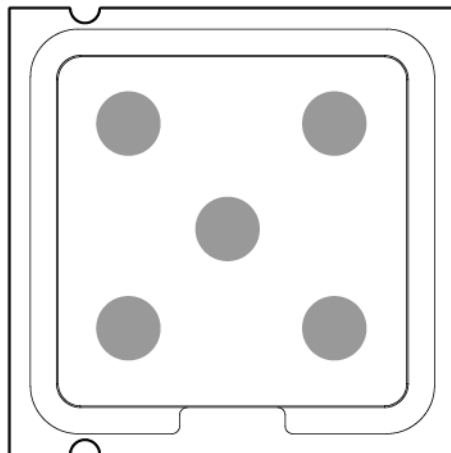


CAUTION: Be sure to close the processor socket retaining bracket before closing the processor locking lever. The lever should close without resistance. Forcing the lever closed can damage the processor and socket, requiring system board replacement.

9. Close the processor retaining bracket, and then secure the processor locking lever.



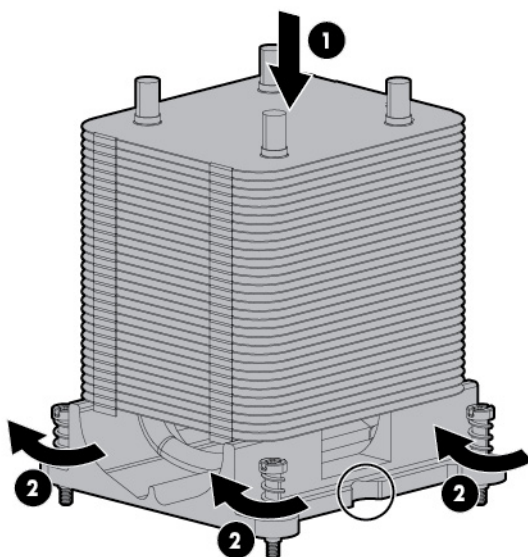
10. Clean the old thermal grease from the heatsink and the top of the processor with the alcohol swab. Allow the alcohol to evaporate before continuing.
11. Apply all the grease to the top of the processor in the following pattern to ensure even distribution.





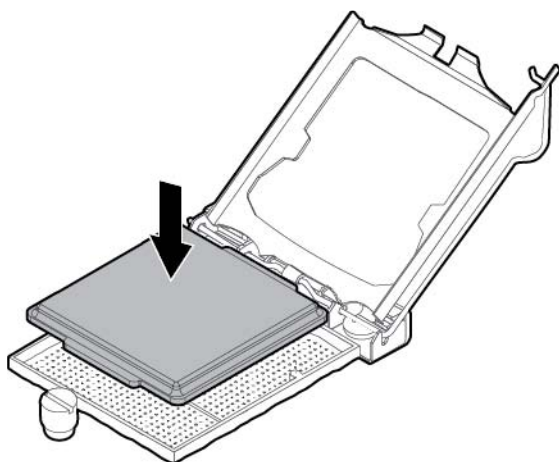
CAUTION: Do not overtighten the screws as this might damage the board, connectors, or screws and voids the warranty of the board.

12. Install the heatsink:
 - a. Position the heatsink using the guide pin on the processor backplate.
 - b. Tighten one pair of diagonally opposite screws halfway, and then tighten the other pair of screws.
 - c. Finish the installation by completely tightening the screws in the same sequence.



CAUTION: When returning a damaged system board to HP, always install all processor socket covers to prevent damage to the processor sockets and system board.

13. Install the processor socket cover on the failed system board.



14. Connect all cables disconnected from the failed system board.
15. Install the capacitor pack.
16. Install the rear system fan.
17. Install the air baffle.
18. Install the access panel.

19. Lock the tower bezel.
20. Connect each power cord to the server.
21. Connect each power cord to the power source.
22. Press the Power On/Standby button.

The server exits standby mode and applies full power to the system. The system power LED changes from amber to green.

After you replace the system board, you must re-enter the server serial number and the product ID.

1. During the server startup sequence, press the **F9** key to access RBSU.
2. Select the **Advanced Options** menu.
3. Select **Service Options**.
4. Select **Serial Number**. The following warning appears:
Warning: The serial number should ONLY be modified by qualified service personnel. This value should always match the serial number located on the chassis.
5. Press the **Enter** key to clear the warning.
6. Enter the serial number and press the **Enter** key.
7. Select **Product ID**. The following warning appears:
Warning: The Product ID should ONLY be modified by qualified service personnel. This value should always match the Product ID located on the chassis.
8. Enter the product ID and press the **Enter** key.
9. Press the **Esc** key to close the menu.
10. Press the **Esc** key to exit RBSU.
11. Press the **F10** key to confirm exiting RBSU. The server automatically reboots.

HP Trusted Platform Module

The TPM is not a customer-removable part.



CAUTION: Any attempt to remove an installed TPM from the system board breaks or disfigures the TPM security rivet. Upon locating a broken or disfigured rivet on an installed TPM, administrators should consider the system compromised and take appropriate measures to ensure the integrity of the system data.

If you suspect a TPM board failure, leave the TPM installed and remove the system board. Contact an HP authorized service provider for a replacement system board and TPM board.

Troubleshooting

Troubleshooting resources

The *HP ProLiant Gen8 Troubleshooting Guide, Volume I: Troubleshooting* provides procedures for resolving common problems and comprehensive courses of action for fault isolation and identification, issue resolution, and software maintenance on ProLiant servers and server blades. To view the guide, select a language:

- English (http://www.hp.com/support/ProLiant_TSG_v1_en)
- French (http://www.hp.com/support/ProLiant_TSG_v1_fr)
- Spanish (http://www.hp.com/support/ProLiant_TSG_v1_sp)
- German (http://www.hp.com/support/ProLiant_TSG_v1_gr)
- Japanese (http://www.hp.com/support/ProLiant_TSG_v1_jp)
- Simplified Chinese (http://www.hp.com/support/ProLiant_TSG_v1_sc)

The *HP ProLiant Gen8 Troubleshooting Guide, Volume II: Error Messages* provides a list of error messages and information to assist with interpreting and resolving error messages on ProLiant servers and server blades. To view the guide, select a language:

- English (http://www.hp.com/support/ProLiant_EMG_v1_en)
- French (http://www.hp.com/support/ProLiant_EMG_v1_fr)
- Spanish (http://www.hp.com/support/ProLiant_EMG_v1_sp)
- German (http://www.hp.com/support/ProLiant_EMG_v1_gr)
- Japanese (http://www.hp.com/support/ProLiant_EMG_v1_jp)
- Simplified Chinese (http://www.hp.com/support/ProLiant_EMG_v1_sc)

Diagnostic tools

HP Insight Diagnostics

HP Insight Diagnostics is a proactive server management tool, available in both offline and online versions, that provides diagnostics and troubleshooting capabilities to assist IT administrators who verify server installations, troubleshoot problems, and perform repair validation.

HP Insight Diagnostics Offline Edition performs various in-depth system and component testing while the OS is not running. To run this utility, boot the server using Intelligent Provisioning.

HP Insight Diagnostics Online Edition is a web-based application that captures system configuration and other related data needed for effective server management. Available in Microsoft Windows and Linux versions, the utility helps to ensure proper system operation.

For more information or to download the utility, see the HP website (<http://www.hp.com/servers/diags>). HP Insight Diagnostics Online Edition is also available in the SPP. For more information, see the HP website (<http://www.hp.com/go/spp/download>).

HP Insight Diagnostics survey functionality

HP Insight Diagnostics (on page 62) provides survey functionality that gathers critical hardware and software information on ProLiant servers.

This functionality supports operating systems that are supported by the server. For operating systems supported by the server, see the HP website (<http://www.hp.com/go/supportos>).

If a significant change occurs between data-gathering intervals, the survey function marks the previous information and overwrites the survey data files to reflect the latest changes in the configuration.

Survey functionality is installed with every Intelligent Provisioning-assisted HP Insight Diagnostics installation, or it can be installed through the SPP.

HP Insight Remote Support software

HP strongly recommends that you install HP Insight Remote Support software to complete the installation or upgrade of your product and to enable enhanced delivery of your HP Warranty, HP Care Pack Service, or HP contractual support agreement. HP Insight Remote Support supplements your monitoring continuously to ensure maximum system availability by providing intelligent event diagnosis, and automatic, secure submission of hardware event notifications to HP, which will initiate a fast and accurate resolution, based on your product's service level. Notifications may be sent to your authorized HP Channel Partner for onsite service, if configured and available in your country.

The HP Insight Remote Support software extends the HP enterprise remote support portfolio for customers with small and medium size IT environments. The software is available in two variants:

- **HP Insight Remote Support 7.x software** is optimized to support up to 500 managed systems and can be installed on a Windows ProLiant hosting device or a Windows ESXi Virtual Machine. It can be integrated easily to work with a supported version of HP Systems Insight Manager. HP Insight Remote

Support 7.x provides anytime, anywhere personalized access to your IT environment through HP Insight Online, and is also the recommended version for HP Proactive Care Service.

- **HP Insight Remote Support Advanced** supports medium-sized to large environments with up to 3,500 devices. It can be installed on a Windows ProLiant hosting device or a Windows ESXi Virtual Machine and requires HP Systems Insight Manager. Optionally, customers using HP Operations Manager or SAP Solution Manager to manage their environment can integrate these platforms easily to create a single view. This software is also optimized to deliver Mission Critical Services through additional features.

For more information about the Insight Remote Support Advanced software, see the HP website (<http://www.hp.com/go/insightremotesupport>).

The *HP Insight Remote Support Release Notes* detail the prerequisites, supported hardware, and associated operating systems. The release notes are available on the HP website (<http://www.hp.com/go/insightremotesupport/docs>). HP Insight Remote Support is included as part of HP Warranty, HP Care Pack Service, or HP contractual support agreement.

HP ROM-Based Setup Utility

RBSU is a configuration utility embedded in HP ProLiant servers that performs a wide range of configuration activities that can include the following:

- Configuring system devices and installed options
- Enabling and disabling system features
- Displaying system information
- Selecting the primary boot controller
- Configuring memory options
- Language selection

For more information on RBSU, see the *HP ROM-Based Setup Utility User Guide* on the Documentation CD or the HP website (<http://www.hp.com/support/smartstart/documentation>).

Integrated Management Log

The IML records hundreds of events and stores them in an easy-to-view form. The IML timestamps each event with 1-minute granularity.

You can view recorded events in the IML in several ways, including the following:

- From within HP SIM
- From within operating system-specific IML viewers
 - For Windows: IML Viewer
 - For Linux: IML Viewer Application
- From within the iLO user interface
- From within HP Insight Diagnostics (on page [62](#))

USB support and functionality

USB support

HP provides both standard USB 2.0 support and legacy USB 2.0 support. Standard support is provided by the OS through the appropriate USB device drivers. Before the OS loads, HP provides support for USB devices through legacy USB support, which is enabled by default in the system ROM.

Legacy USB support provides USB functionality in environments where USB support is not available normally. Specifically, HP provides legacy USB functionality for the following:

- POST
- RBSU
- Diagnostics
- DOS
- Operating environments which do not provide native USB support

Internal USB functionality

An internal USB connector is available for use with security key devices and USB drive keys. This solution provides for use of a permanent USB key installed in the internal connector, avoiding issues of clearance on the front of the rack and physical access to secure data.

External USB functionality

HP provides external USB support to enable local connection of USB devices for server administration, configuration, and diagnostic procedures.

For additional security, external USB functionality can be disabled through RBSU.

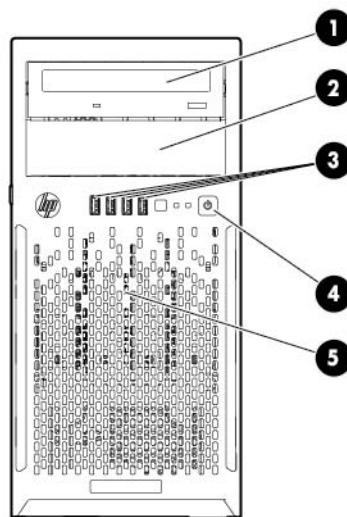
Automatic Server Recovery

ASR is a feature that causes the system to restart when a catastrophic operating system error occurs, such as a blue screen, ABEND (does not apply to HP ProLiant DL980 Servers), or panic. A system fail-safe timer, the ASR timer, starts when the System Management driver, also known as the Health Driver, is loaded. When the operating system is functioning properly, the system periodically resets the timer. However, when the operating system fails, the timer expires and restarts the server.

ASR increases server availability by restarting the server within a specified time after a system hang. At the same time, the HP SIM console notifies you by sending a message to a designated pager number that ASR has restarted the system. You can disable ASR from the System Management Homepage or through RBSU.

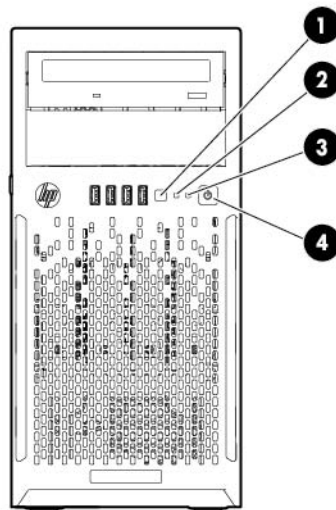
Component identification

Front panel components



Item	Description
1	Optical drive (optional)
2	Media drive bay
3	USB connectors
4	Power On/Standby button and system power LED
5	Drive bays (inside)

Front panel LEDs and buttons

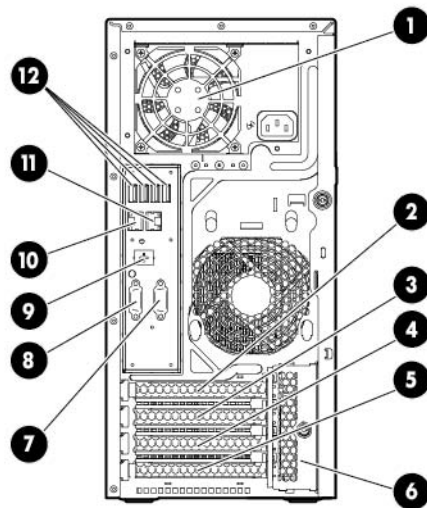


Item	Description	Status
1	UID button/LED	Solid blue = Activated Flashing blue (1 Hz/cycle per sec) = Remote management or firmware upgrade in progress Off = Deactivated
2	Health LED	Solid green = Normal Flashing amber = System degraded Flashing red (1 Hz/cycle per sec) = System critical Fast-flashing red (4 Hz/cycles per sec) = Power fault*
3	NIC status LED	Solid green = Link to network Flashing green (1 Hz/cycle per sec) = Network active Off = No network activity
4	Power On/Standby button and system power LED	Solid green = System on Flashing green (1 Hz/cycle per sec) = Performing power on sequence Solid amber = System in standby Off = No power present**

*To identify components in a degraded or critical state, see the Systems Insight Display LEDs, check iLO/BIOS logs, and reference the server troubleshooting guide.

**Facility power is not present, power cord is not attached, no power supplies are installed, power supply failure has occurred, or the power button cable is disconnected.

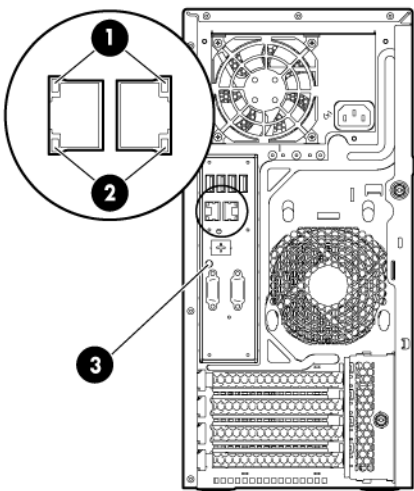
Rear panel components



Item	Description
1	Non-hot-plug power supply
2	Slot 4 PCIe x16 (8, 4, 1)*
3	Slot 3 PCIe x8 (8, 4, 1)*
4	Slot 2 PCIe x8 (4, 1)*
5	Slot 1 PCIe x4 (1)*
6	Expansion slot cover retainer
7	Serial connector
8	Video connector
9	Dedicated iLO management port (optional)
10	NIC 1/shared iLO management connector
11	NIC connector 2
12	USB connectors

* For more information on the expansion slot specifications, see "PCIe expansion slot definitions (on page [70](#))."

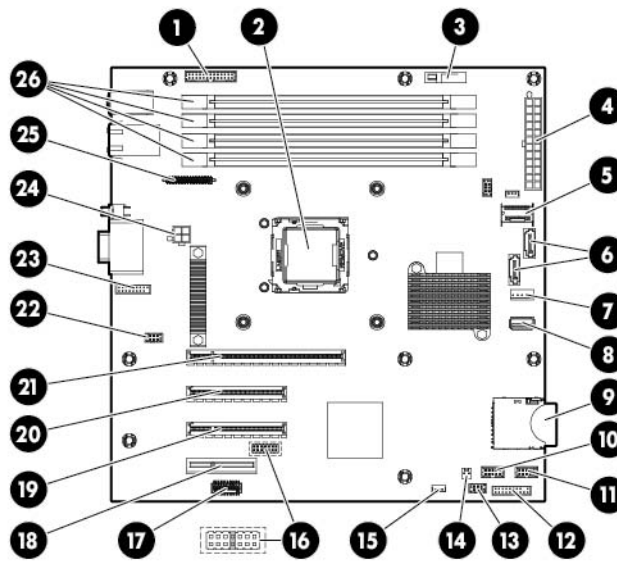
Rear panel LEDs and buttons



Item	Description	Status
1	NIC link LED	Green = Link exists Off = No link exists
2	NIC status LED	Green = Activity exists Flashing green = Activity exists Off = No activity exists
3	UID LED button	Blue = Identification is activated Flashing blue = System is being managed remotely Off = Identification is deactivated
4	Power supply LED (for hot-plug HP CS power supplies only)*	Green = Normal Off = One or more of the following conditions exists: <ul style="list-style-type: none">• Power is unavailable• Power supply failed• Power supply is in standby mode• Power supply error

*Not shown

System board components

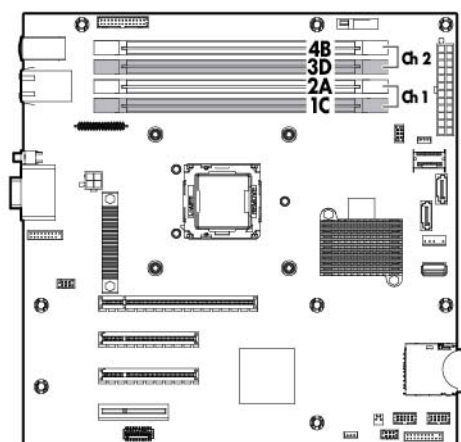


Item	Description
1	RPS connector
2	Processor socket
3	System battery
4	24-pin power supply connector
5	Mini-SAS connector
6	SATA connectors
7	Internal USB cable connector
8	Internal USB connector
9	SD card slot
10	Front USB connector 2
11	Front USB connector 1
12	Front panel LED connector
13	Fan connector 2
14	Reserved
15	Ambient thermal sensor connector
16	NMI header
17	System maintenance switch
18	Slot 1 PCIe x4 (1)*
19	Slot 2 PCIe x8 (4, 1)*
20	Slot 3 PCIe x8 (8, 4, 1)*
21	Slot 4 PCIe x16 (8, 4, 1)*
22	Fan connector 1
23	TPM connector
24	4-pin power supply connector
25	Dedicated iLO module connector
26	DIMM slots

* For more information on the expansion slot specifications, see "PCIe expansion slot definitions (on page 70)."

DIMM slot locations

DIMM slots are numbered sequentially (1 through 4) for the processor. The supported AMP modes use the letter assignments for population guidelines.



PCIe expansion slot definitions

The transfer rate of the PCIe expansion slots 3 and 4 depends on the processor model installed. The slots can either run in PCIe2 (5 GT/s) or PCIe3 (8 GT/s) rate.

- Intel Xeon Processor E3-xxxx Series, Intel Core i3 Processor Series, Intel Pentium G2120, and Intel Celeron G540

Slot number	Type	Length	Height	Connector link width	Negotiable link width
1	PCIe2	Half	Full	x4	x1
2	PCIe2	Full	Full	x8	x4
3	PCIe2	Full	Full	x8	x8
4	PCIe2	Full	Full	x16	x8

- Intel Xeon Processor E3-xxxxV2 Series

Slot number	Type	Length	Height	Connector link width	Negotiable link width
1	PCIe2	Half	Full	x4	x1
2	PCIe2	Full	Full	x8	x4
3	PCIe3	Full	Full	x8	x8
4	PCIe3	Full	Full	x16	x8

System maintenance switch

Position	Default	Function
S1	Off	Off = iLO security is enabled. On = iLO security is disabled.

Position	Default	Function
S2	Off	Off = System configuration can be changed. On = System configuration is locked.
S3	Off	Reserved
S4	Off	Reserved
S5	Off	Off = Power-on password is enabled. On = Power-on password is disabled.
S6	Off	Off = No function On = ROM reads system configuration as invalid.
S7	—	Reserved
S8	—	Reserved
S9	—	Reserved
S10	—	Reserved
S11	—	Reserved
S12	—	Reserved

To access redundant ROM, set S1, S5, and S6 to on.

When the system maintenance switch position 6 is set to the On position, the system is prepared to erase all system configuration settings from both CMOS and NVRAM.



CAUTION: Clearing CMOS and/or NVRAM deletes configuration information. Be sure to properly configure the server or data loss could occur.

NMI functionality

An NMI crash dump creates a crash dump log before resetting a system which is not responding.

Crash dump log analysis is an essential part of diagnosing reliability problems, such as failures of operating systems, device drivers, and applications. Many crashes freeze a system, and the only available action for administrators is to restart the system. Resetting the system erases any information which could support problem analysis, but the NMI feature preserves that information by performing a memory dump before a system reset.

To force the system to invoke the NMI handler and generate a crash dump log, do one of the following:

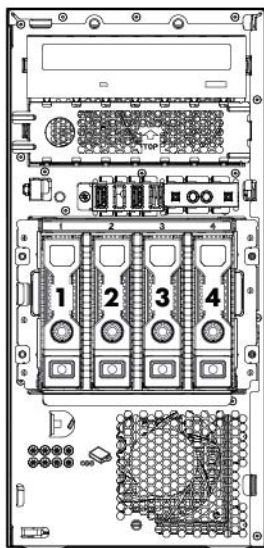
- Use the iLO Virtual NMI feature.
- Short the NMI header ("System board components" on page 69).

For more information, see the HP website

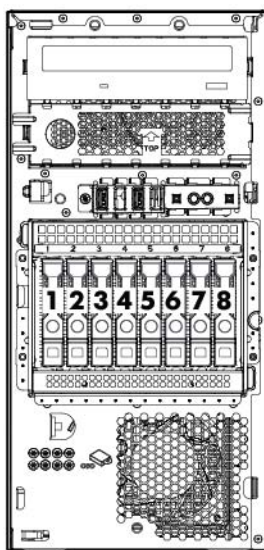
(<http://h20000.www2.hp.com/bc/docs/support/SupportManual/c00797875/c00797875.pdf>).

Drive numbering

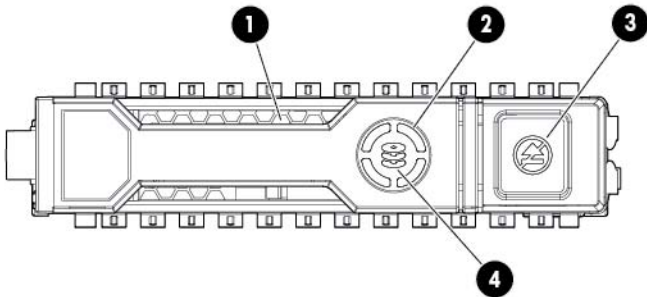
- Four-bay LFF drive model



- Eight-bay SFF drive model



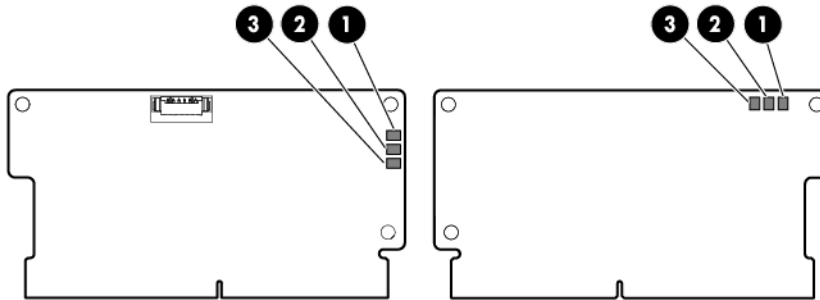
Hot-plug drive LED definitions



Item	LED	Status	Definition
1	Locate	Solid blue	The drive is being identified by a host application.
		Flashing blue	The drive carrier firmware is being updated or requires an update.
2	Activity ring	Rotating green	Drive activity
		Off	No drive activity
3	Do not remove	Solid white	Do not remove the drive. Removing the drive causes one or more of the logical drives to fail.
		Off	Removing the drive does not cause a logical drive to fail.
4	Drive status	Solid green	The drive is a member of one or more logical drives.
		Flashing green	The drive is rebuilding or performing a RAID migration, stripe size migration, capacity expansion, or logical drive extension, or is erasing.
		Flashing amber/green	The drive is a member of one or more logical drives and predicts the drive will fail.
		Flashing amber	The drive is not configured and predicts the drive will fail.
		Solid amber	The drive has failed.
		Off	The drive is not configured by a RAID controller.

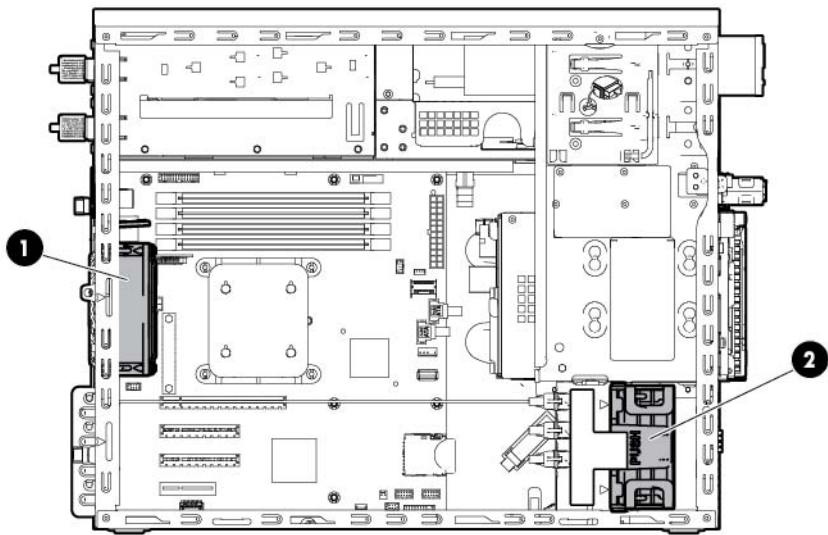
FBWC module LED definitions

The FBWC module has three single-color LEDs (one amber and two green). The LEDs are duplicated on the reverse side of the cache module to facilitate status viewing.



1 - Amber	2 - Green	3 - Green	Interpretation
Off	Off	Off	The cache module is not powered.
Off	Flashing 0.5 Hz	Flashing 0.5 Hz	The cache microcontroller is executing from within its boot loader and receiving new flash code from the host controller.
Off	Flashing 1 Hz	Flashing 1 Hz	The cache module is powering up, and the capacitor pack is charging.
Off	Off	Flashing 1 Hz	The cache module is idle, and the capacitor pack is charging.
Off	Off	On	The cache module is idle, and the capacitor pack is charged.
Off	On	On	The cache module is idle, the capacitor pack is charged, and the cache contains data that has not yet been written to the drives.
Off	Flashing 1 Hz	Off	A backup is in progress.
Off	On	Off	The current backup is complete with no errors.
Flashing 1 Hz	Flashing 1 Hz	Off	The current backup failed, and data has been lost.
Flashing 1 Hz	Flashing 1 Hz	On	A power error occurred during the previous or current boot. Data may be corrupt.
Flashing 1 Hz	On	Off	An overtemperature condition exists.
Flashing 2 Hz	Flashing 2 Hz	Off	The capacitor pack is not attached.
Flashing 2 Hz	Flashing 2 Hz	On	The capacitor has been charging for 10 minutes, but has not reached sufficient charge to perform a full backup.
On	On	Off	The current backup is complete, but power fluctuations occurred during the backup.
On	On	On	The cache module microcontroller has failed.

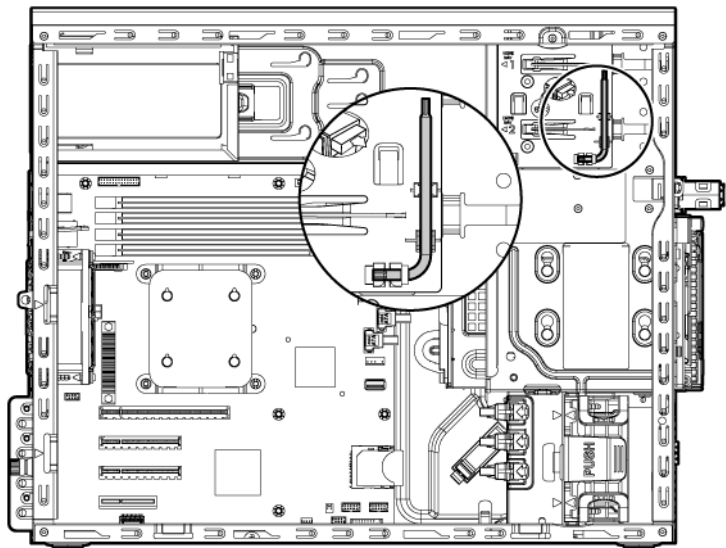
Fan locations



Item	Description
1	Rear system fan (fan 1, for processor cooling)
2	Front system fan (fan 2, for expansion board cooling)

T-10/T-15 Torx screwdriver

The server includes a T-10/T-15 Torx screwdriver located on the side of the media drive cage. Use the screwdriver to loosen screws during hardware configuration procedures.



Cabling

Cabling overview

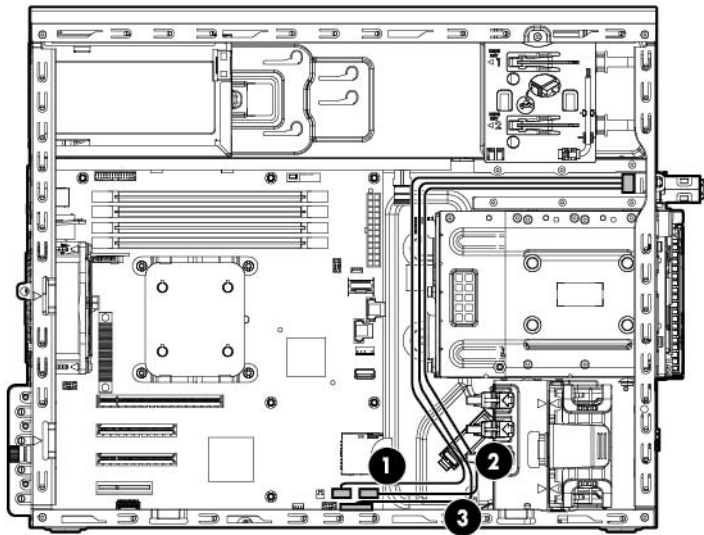
This section provides guidelines that help you make informed decisions about cabling the server and hardware options to optimize performance.

For information on cabling peripheral components, refer to the white paper on high-density deployment at the HP website (<http://www.hp.com/products/servers/platforms>).



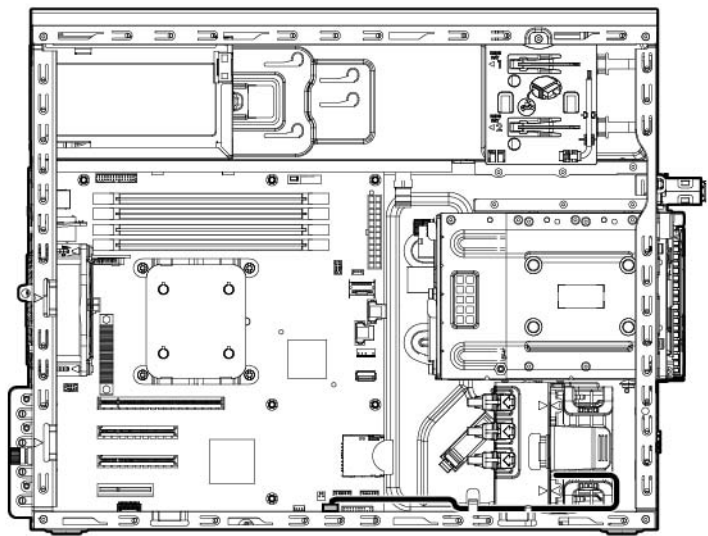
CAUTION: When routing cables, always be sure that the cables are not in a position where they can be pinched or crimped.

Front panel cabling



Item	Description
1	Front USB 2 cable
2	Front USB 1 cable
3	Front panel LED cable

System fan cabling

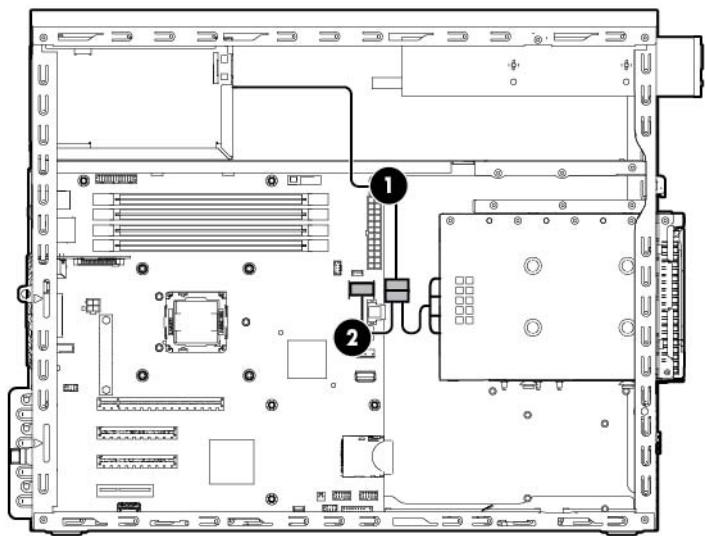


Item	Description
1	Rear system fan cable
2	Front system fan cable

Storage cabling

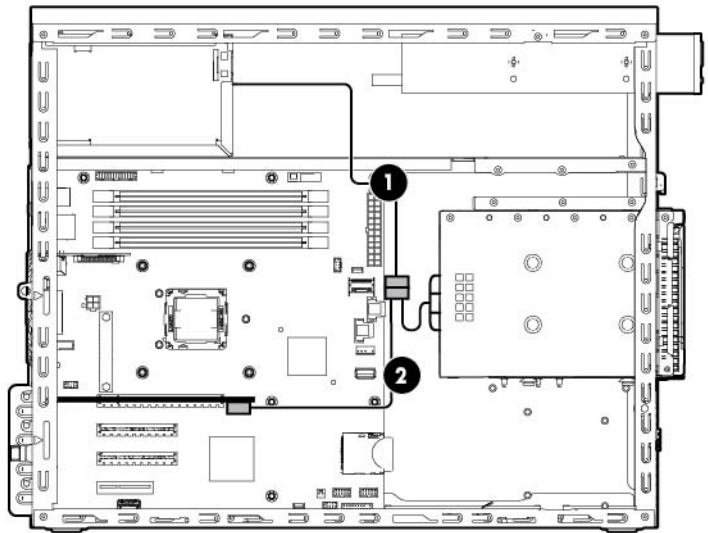
Four-bay LFF drive cabling

Non-hot-plug, SATA drive support only



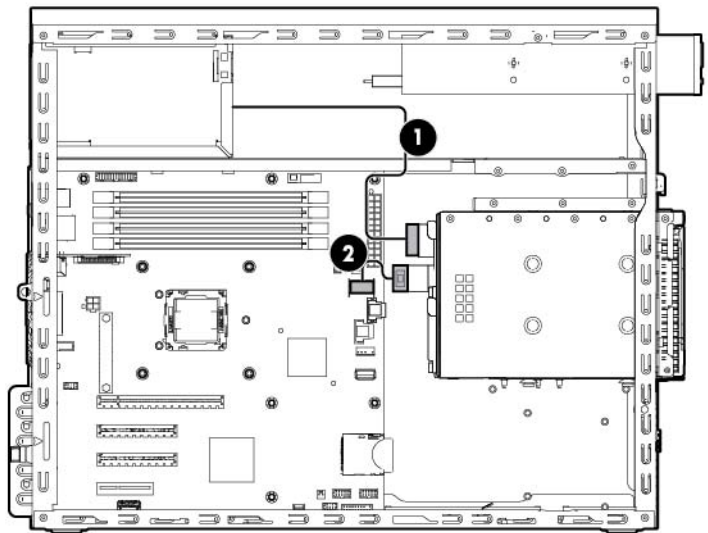
Item	Description
1	Power cable
2	Data cable

Non-hot-plug, SATA and SAS drive support



Item	Description
1	Power cable
2	Data cable

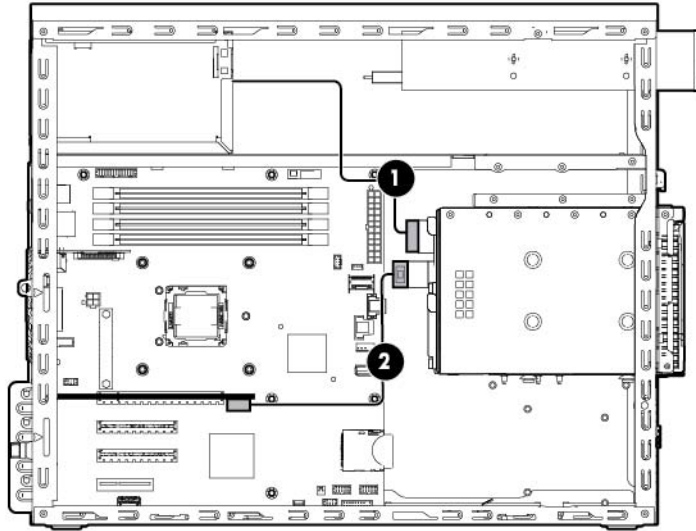
Hot-plug, SATA drive support



Item	Description
1	Power cable

Item	Description
2	Mini-SAS cable

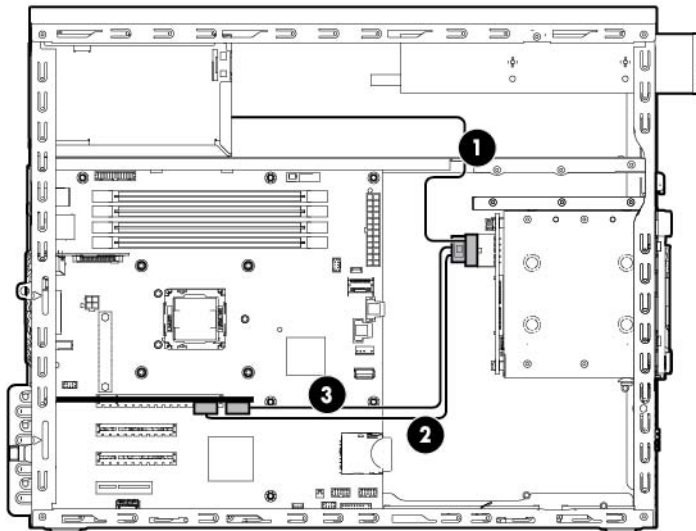
Hot-plug, SATA and SAS drive support



Item	Description
1	Power cable
2	Mini-SAS cable

Eight-bay SFF drive cabling

This drive configuration supports hot-plug SATA and SAS drives.

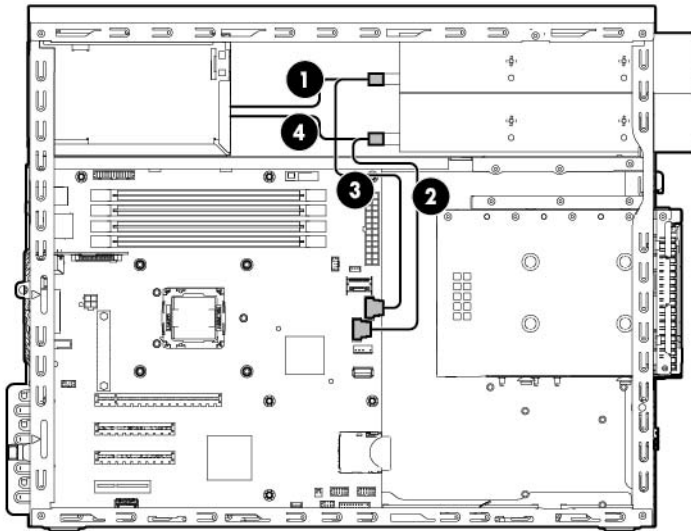


Item	Description
1	Power cable

Item	Description
2	Mini-SAS cable
3	Mini-SAS cable

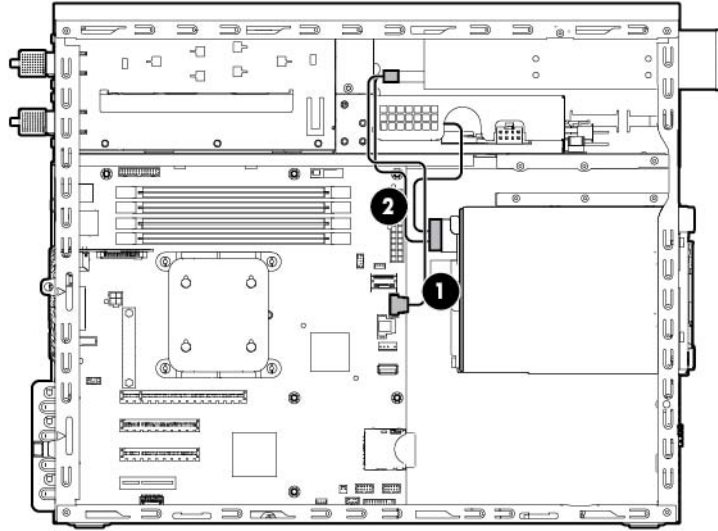
Media drive cabling

- Media drives in a nonredundant power configuration



Item	Description
1	Upper media drive power cable
2	Lower media drive SATA cable
3	Upper media drive SATA cable
4	Lower media drive power cable

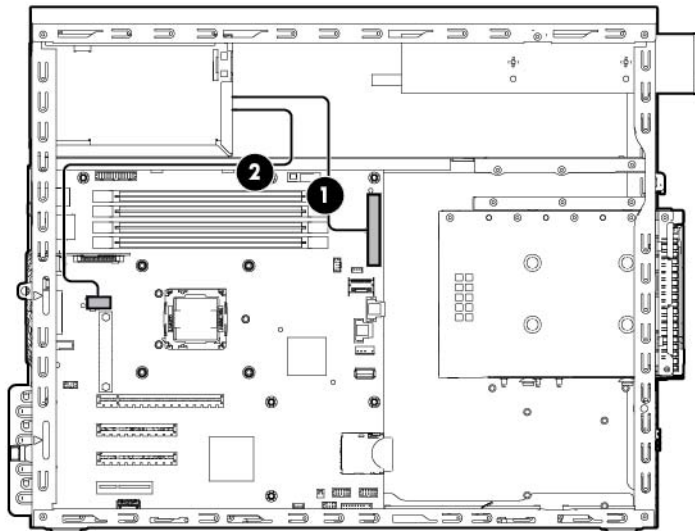
- Media drive in a redundant power configuration



Item	Description
1	Upper media drive SATA cable
2	Upper media drive power cable

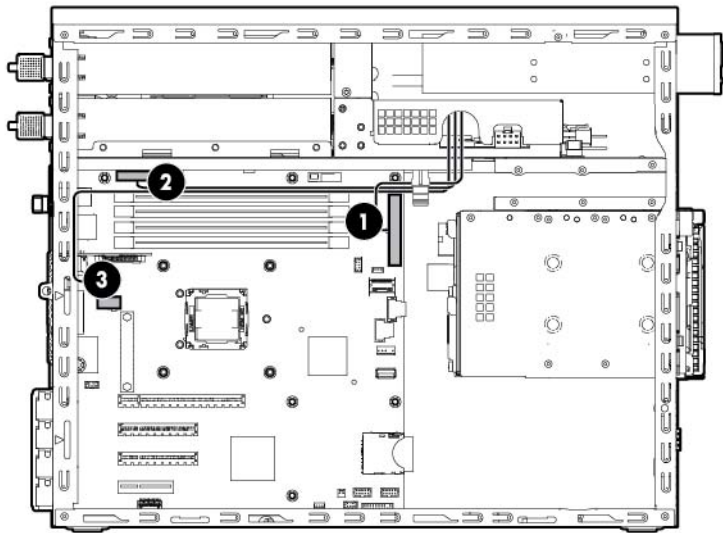
Power supply cabling

Nonredundant power supply cabling



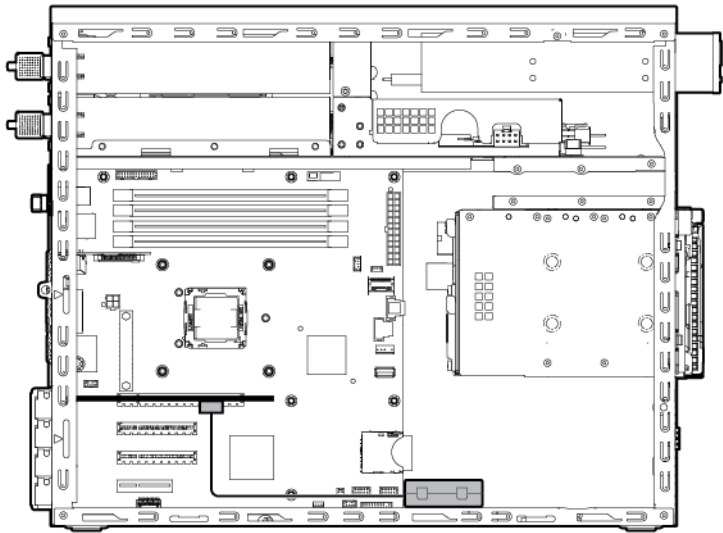
Item	Description
1	24-pin power supply cable
2	4-pin power supply cable

Redundant power supply cabling



Item	Description
1	24-pin power supply cable
2	26-pin RPS cable
3	4-pin power supply cable (with the 8-pin to 4-pin adapter cable connected)

Capacitor pack cabling



Specifications

Environmental specifications

Specification	Value
Temperature range*	
Operating	10°C to 35°C (50°F to 95°F)
Nonoperating	-30°C to 60°C (-22°F to 140°F)
Relative humidity (noncondensing)	
Operating, maximum wet bulb temperature of 28°C (82.4°F)	10% to 90%
Nonoperating, maximum wet bulb temperature of 38.7°C (101.7°F)	5% to 95%

* All temperature ratings shown are for sea level. An altitude derating of 1°C per 304.8 m (1.8°F per 1,000 ft) to 3048 m (10,000 ft) is applicable. No direct sunlight allowed.

Server specifications

Specification	Tower model	Rack model
Height	36.82 cm (14.50 in)	17.50 cm (6.89 in)
Depth	47.52 cm (18.71 in)	47.52 cm (18.71 in)
Width	17.50 cm (6.89 in)	36.82 cm (14.50 in)
Weight, minimum for SFF drive cage	11.00 kg (24.22 lb)	11.00 kg (24.22 lb)
Weight, maximum for SFF drive cage	17.00 kg (37.44 lb)	17.00 kg (37.44 lb)
Weight, minimum for LFF drive cage	11.90 kg (26.21 lb)	11.90 kg (26.21 lb)
Weight, maximum for LFF drive cage	19.00 kg (41.85 lb)	19.00 kg (41.85 lb)

Power supply specifications

Depending on installed options, the server is configured with one of the following power supplies:

- HP 350 W 4U Integrated Power Supply
- HP 460 W CS Gold Hot-plug Power Supply (92% efficiency)



CAUTION: Check the system and power supply input ratings before powering up the server.

HP 350 W 4U Integrated Power Supply

Specification	Value
Input requirements	—
Rated input voltage	100 V AC to 240 V AC
Rated input frequency	47 Hz to 63 Hz
Rated input current	6 A
Rated input power	440 W at 100 V AC input 440 W at 200 V AC input
Efficiency	No less than 82% at 100% load No less than 85% at 50% load No less than 82% at 20% load
Power supply output	—
Rated steady-state power	350 W at 100 V AC input 350 W at 200 V AC input
Maximum peak power	400 W at 100 V AC input 400 W at 200 V AC input
Rated output power	350 W

HP 460 W CS Gold Hot-plug Power Supply (92% efficiency)

Specification	Value
Input requirements	—
Rated input voltage	100 V AC to 240 V AC
Rated input frequency	50 Hz to 60 Hz
Rated input current	6 A to 3 A
Rated input power	526 W at 115 V AC input 523 W at 230 V AC input
Power supply output	—
Efficiency	Not less than 87.5% at 100% load Not less than 89.5% at 50% load Not less than 87.5% at 20% load
Rated steady-state power	460 W at 100 V to 120 V AC input 460 W at 200 V to 240 V AC input
Maximum peak power	460 W at 100 V to 120 V AC input 460 W at 200 V to 240 V AC input

Hot-plug power supply calculations

For hot-plug power supply specifications and calculators to determine electrical and heat loading for the server, see the HP Power Advisor website (<http://www.hp.com/go/hppoweradvisor>).

Support and other resources

Before you contact HP

Be sure to have the following information available before you call HP:

- Active Health System log (HP ProLiant Gen8 or later products)
Download and have available an Active Health System log for 3 days before the failure was detected. For more information, see the *HP iLO 4 User Guide* or *HP Intelligent Provisioning User Guide* on the HP website (<http://www.hp.com/go/ilo/docs>).
- Onboard Administrator SHOW ALL report (for HP BladeSystem products only)
For more information on obtaining the Onboard Administrator SHOW ALL report, see the HP website (<http://www.hp.com/go/OAlog>).
- Technical support registration number (if applicable)
- Product serial number
- Product model name and number
- Product identification number
- Applicable error messages
- Add-on boards or hardware
- Third-party hardware or software
- Operating system type and revision level

HP contact information

For United States and worldwide contact information, see the Contact HP website (<http://www.hp.com/go/assistance>).

In the United States:

- To contact HP by phone, call 1-800-334-5144. For continuous quality improvement, calls may be recorded or monitored.
- If you have purchased a Care Pack (service upgrade), see the Support & Drivers website (<http://www8.hp.com/us/en/support-drivers.html>). If the problem cannot be resolved at the website, call 1-800-633-3600. For more information about Care Packs, see the HP website (<http://pro-aq-sama.houston.hp.com/services/cache/10950-0-0-225-121.html>).

Acronyms and abbreviations

ABEND

abnormal end

AMP

Advanced Memory Protection

ASR

Automatic Server Recovery

CSR

Customer Self Repair

DDR

double data rate

FBWC

flash-backed write cache

HP CS

HP Common Slot (power supply)

HP SIM

HP Systems Insight Manager

iLO

Integrated Lights-Out

IML

Integrated Management Log

LFF

large form factor

MLC

multilevel cell

NMI

nonmaskable interrupt

NVRAM

nonvolatile memory

PCIe

peripheral component interconnect express

POST

Power-On Self Test

RBSU

ROM-Based Setup Utility

RDIMM

registered dual in-line memory module

RPS

redundant power supply

SAS

serial attached SCSI

SATA

serial ATA

SD

Secure Digital

SFF

small form factor

SLC

single-level cell

SPP

HP Service Pack for ProLiant

TPM

Trusted Platform Module

UDIMM

unregistered dual in-line memory module

UID

unit identification

USB

universal serial bus

Documentation feedback

HP is committed to providing documentation that meets your needs. To help us improve the documentation, send any errors, suggestions, or comments to Documentation Feedback (<mailto:docsfeedback@hp.com>). Include the document title and part number, version number, or the URL when submitting your feedback.

Index

A

access panel 31
air baffle 32
ASR (Automatic Server Recovery) 64
authorized reseller 85
Automatic Server Recovery (ASR) 64

B

bezel, tower 26
blanks 27
board components 69

C

cables 76
cabling 76, 77, 78, 79, 80, 81, 82
cache module 45, 74
cache module, removing 45
capacitor pack 45, 46, 82
components 16, 65
components, identification 16, 65
components, system board 69
connectors 65
contacting HP 85
crash dump analysis 71
CSR (customer self repair) 6
customer self repair (CSR) 6, 85

D

diagnostic tools 62, 63, 64
diagnostics utility 62
DIMMs 38, 39
drive blank 27
drive cabling 76, 77, 79
drive cage, removing 33, 34
drive LEDs 73
drives 27, 28, 29, 32, 72, 73

E

electrostatic discharge 24
environmental specifications 83

error messages 61

F

fan module locations 75
fans 37, 50
FBWC cabling 77, 82
FBWC module LEDs 74
features 65
flash-backed write cache procedures 45, 48
front I/O module 36
front panel cabling 76
front panel components 65

G

guidelines, troubleshooting 61

H

hard drive LEDs 73
hard drives, determining status of 73
health driver 64
heatsink 39
help resources 85
HP Insight Diagnostics 62
HP Insight Remote Support software 62
HP technical support 85

I

illustrated parts catalog 16
iLO (Integrated Lights-Out) 50, 51, 63
IML (Integrated Management Log) 63
Insight Diagnostics 62
Integrated Management Log (IML) 63

L

LEDs 73
LEDs, front panel 73
LEDs, hard drive 73
LEDs, rear panel 68
LEDs, SAS hard drive 73
LEDs, troubleshooting 61

M

management tools 62
mechanical components 16
media drive bay cabling 80

N

NMI functionality 71

O

optical drive 32, 65

P

part numbers 16
PCI expansion slots 70
phone numbers 85
power down procedure 26
power supply 30, 51, 53
power supply cabling 81, 82
power supply specifications 83, 84
powering down 26
problem diagnosis 61
processors 41

R

RBSU (ROM-Based Setup Utility) 63
rear components 67
rear panel buttons 68
rear panel components 67
rear panel LEDs 68
removal and replacement procedures 24
required tools 24
resources 85
RPS cabling 52, 53

S

safety considerations 24
SAS and SATA device numbers 72
SAS cabling 78, 79
SATA cabling 77, 78
server, rear panel LEDs 68
server, rear panel components 67
spare part numbers 16
specifications 83, 84
specifications, environmental 83
specifications, mechanical 83
specifications, power 83
specifications, server 83

static electricity 24
support 85
symbols on equipment 24
system battery 49
system board components 69
system board replacement 54, 69
system components 19, 65
system fans 50, 77
system maintenance switch 70

T

technical support 85
telephone numbers 85
tools 24
Torx screwdriver 75
tower bezel, removing 26
troubleshooting 61
Trusted Platform Module (TPM) 60

U

USB support 64
utilities 62
utilities, deployment 63

V

video connector 69

W

warnings 25
website, HP 85
weight 83